

FIG. 1

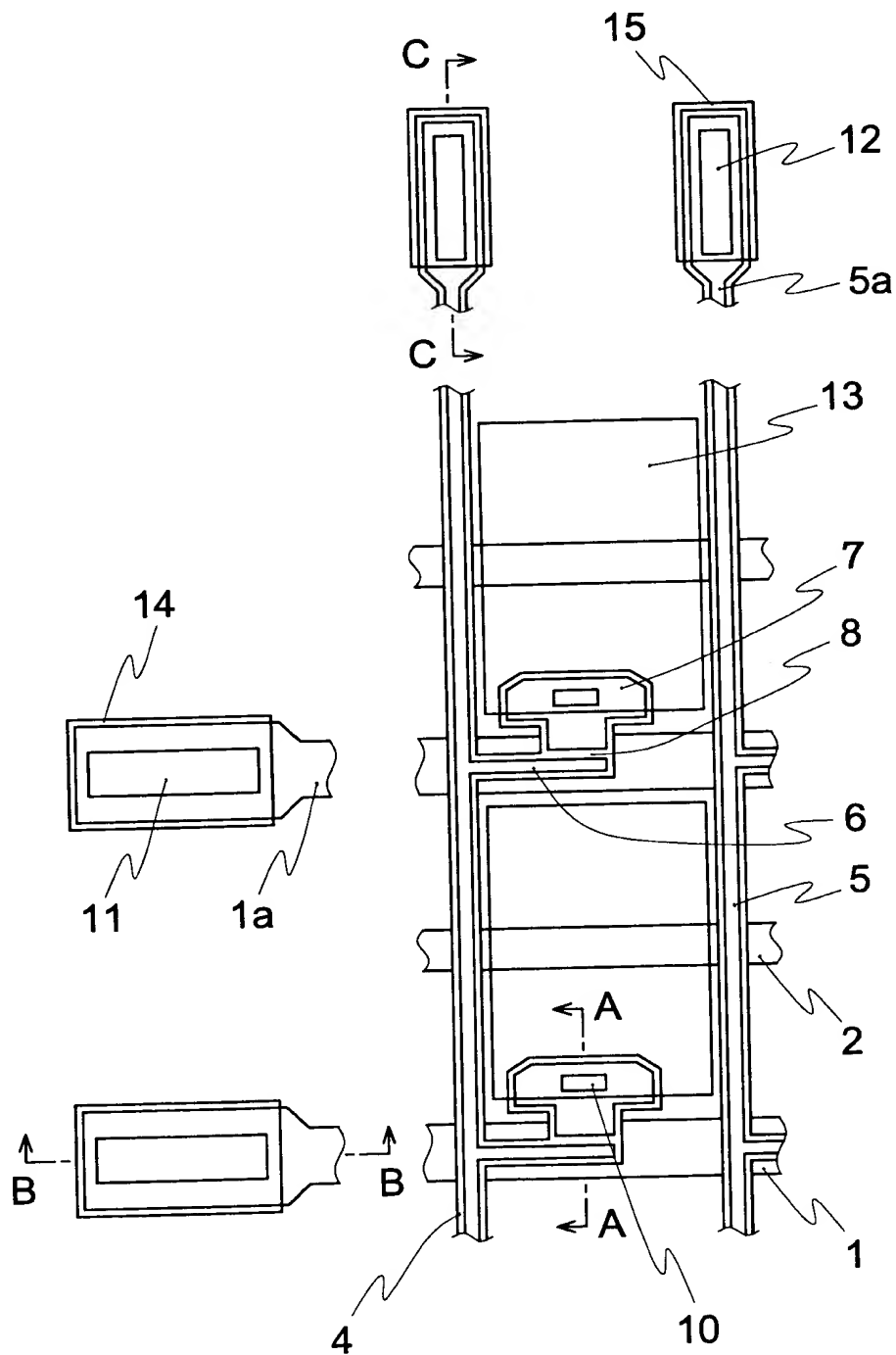


FIG. 2(a)

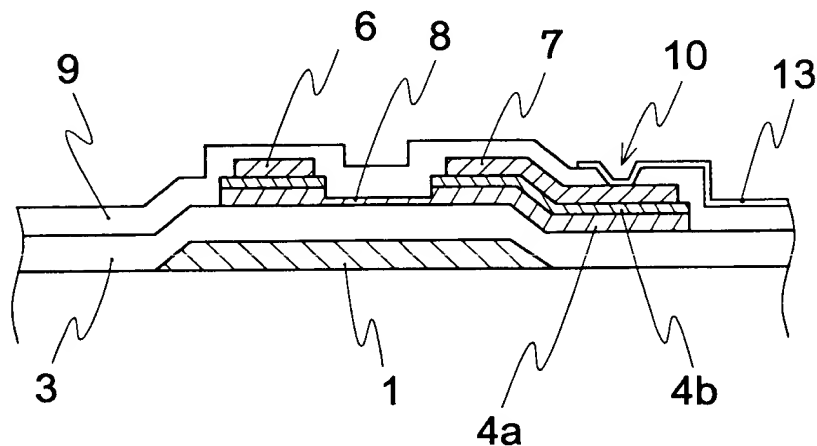


FIG. 2(b)

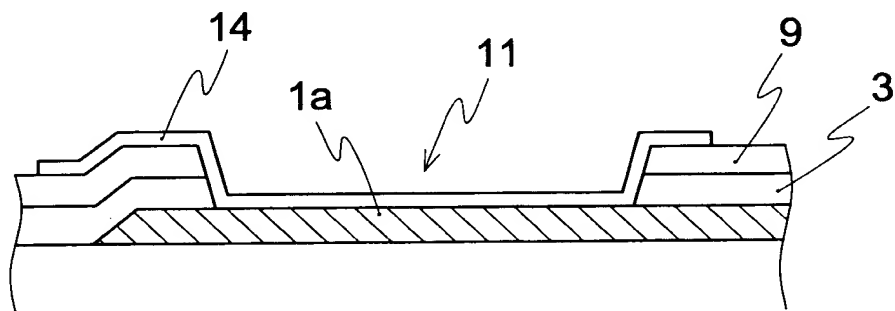


FIG. 2(c)

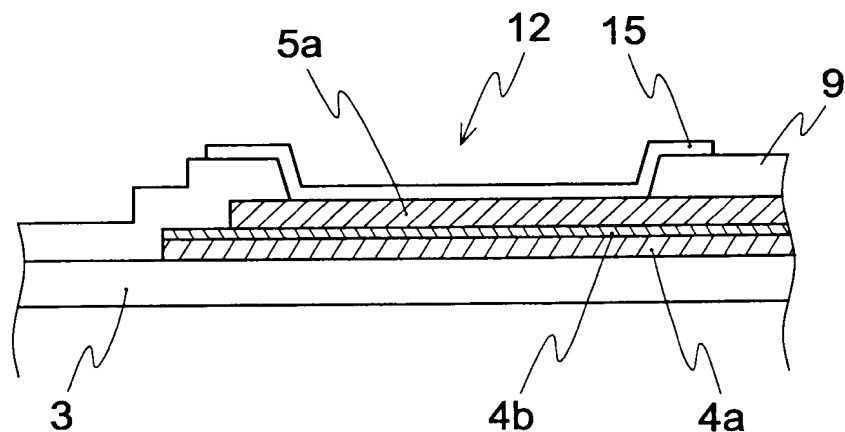


FIG. 2(d)

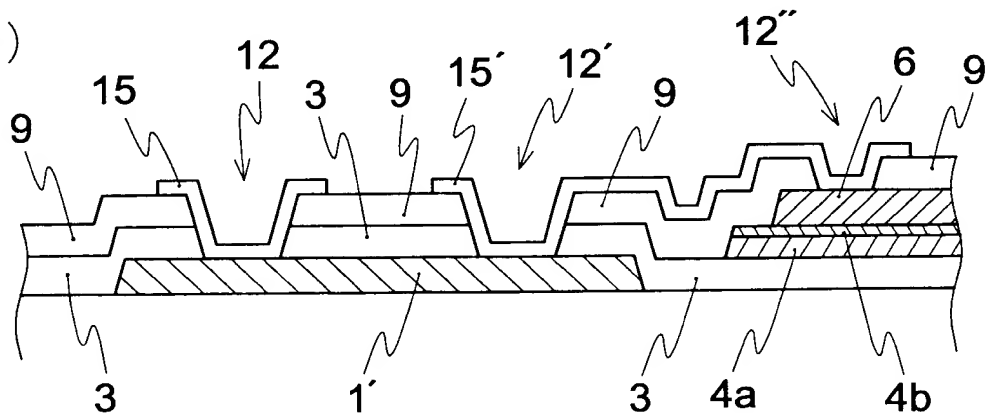


FIG. 3

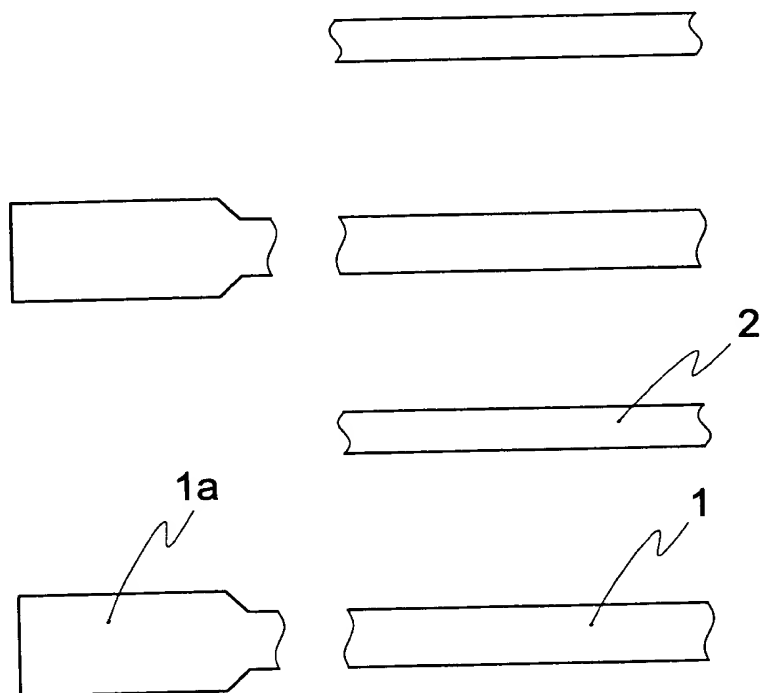


FIG. 4

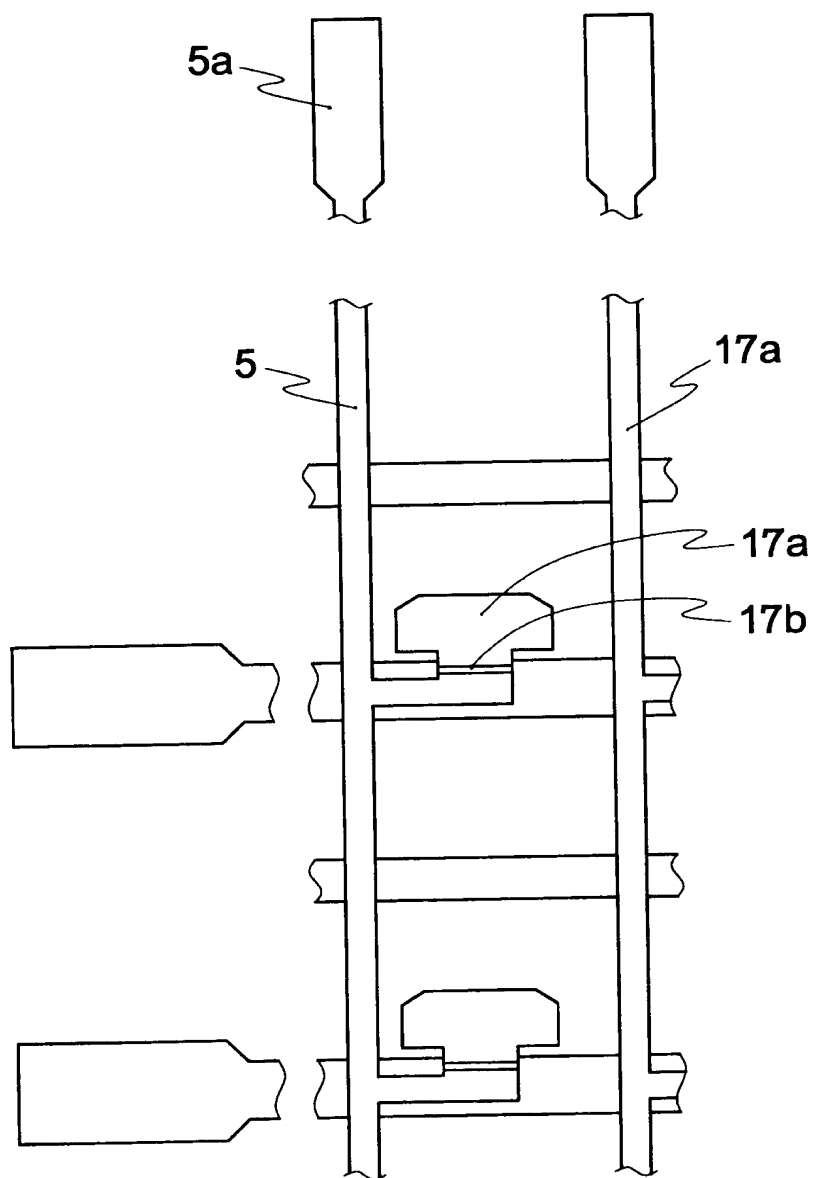


FIG. 5

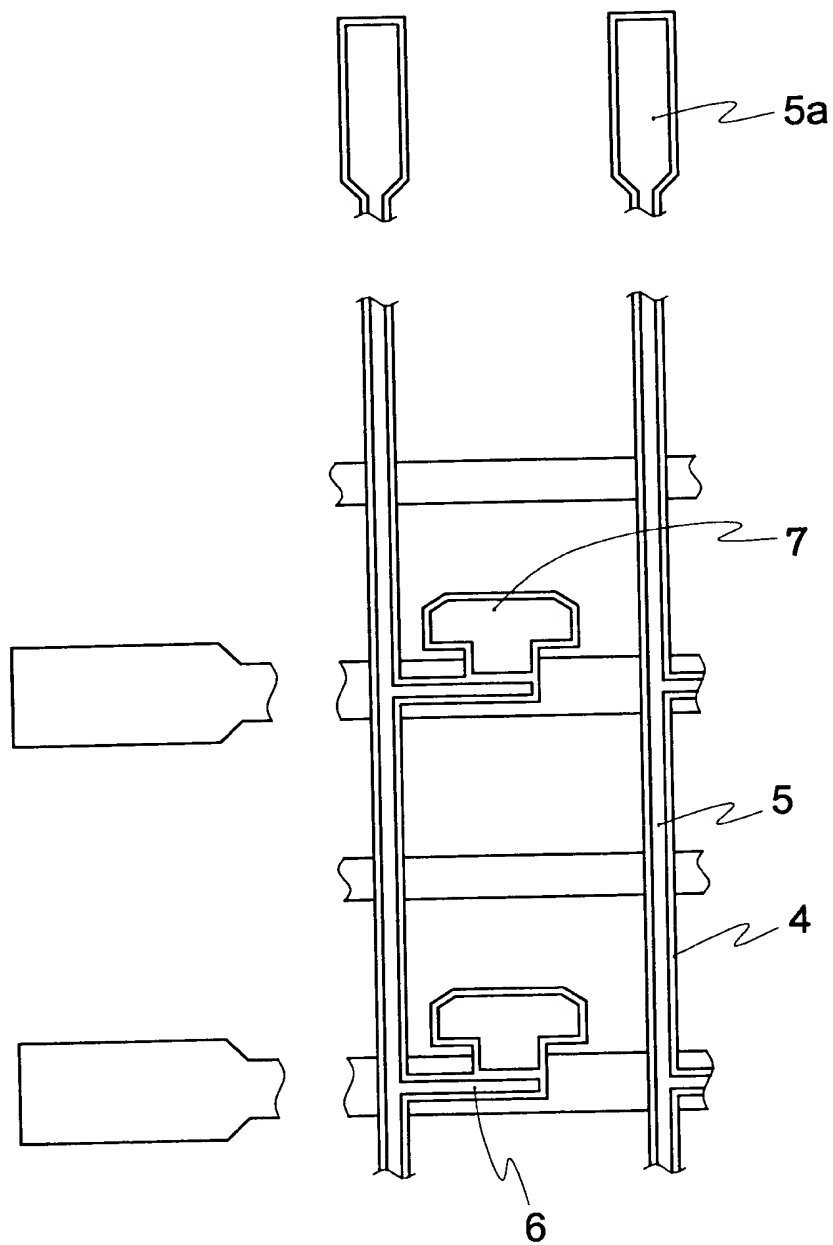


FIG. 6

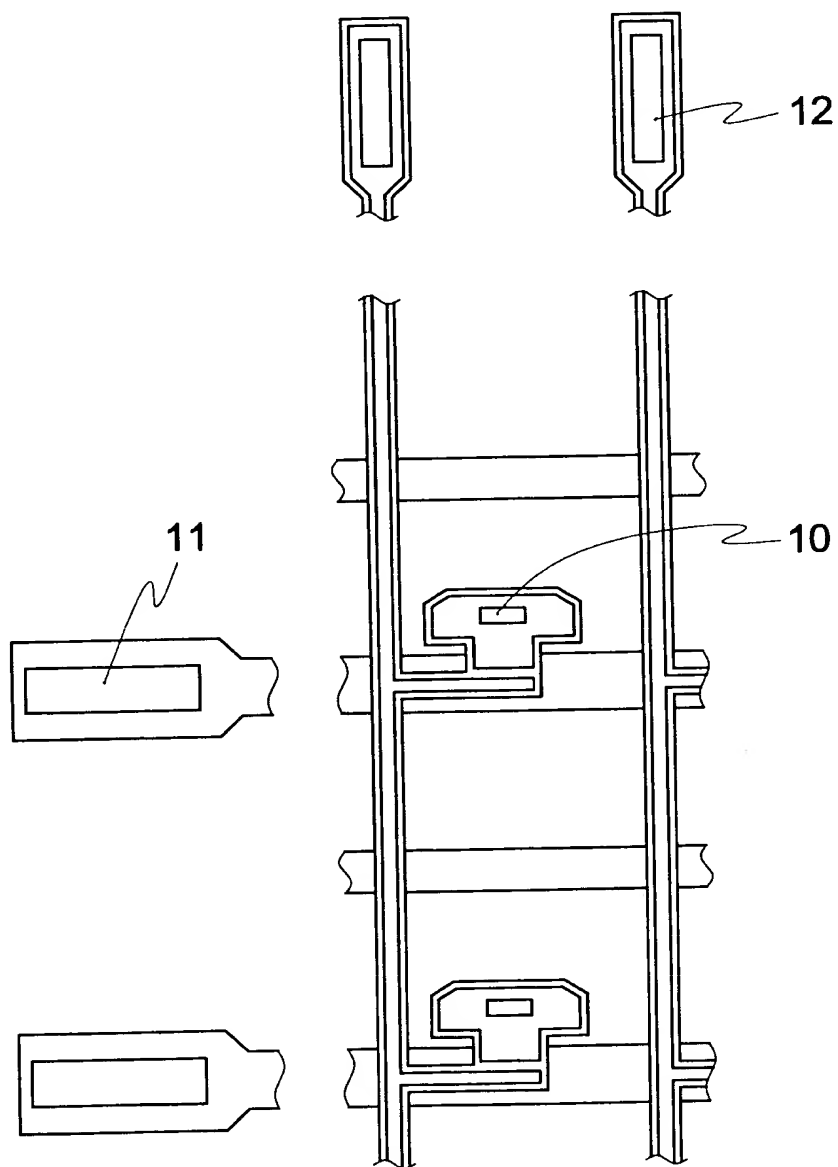


FIG. 7

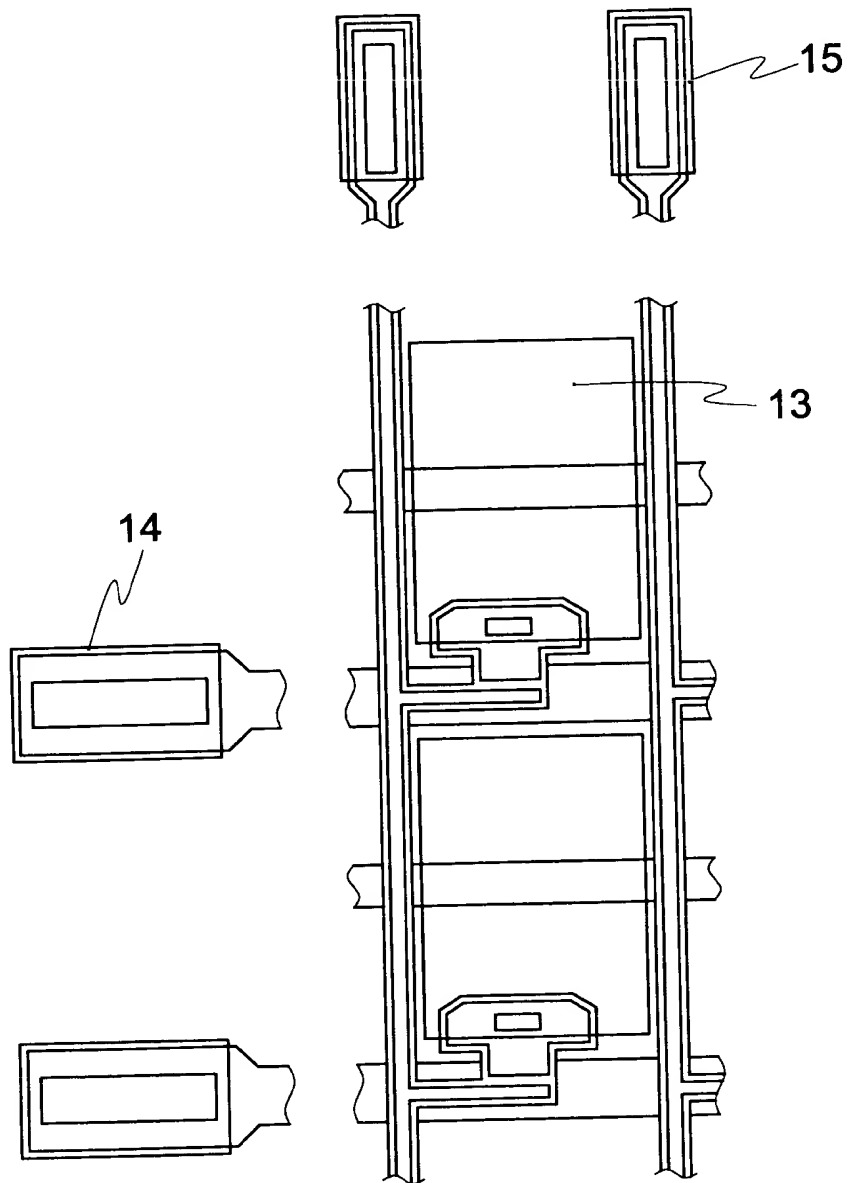


FIG. 8

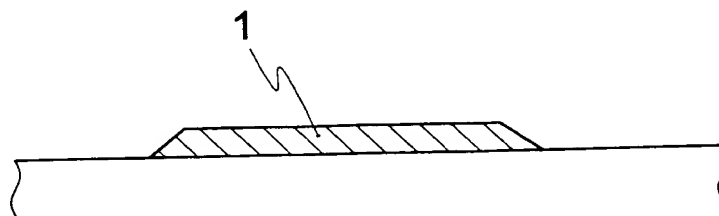


FIG. 12

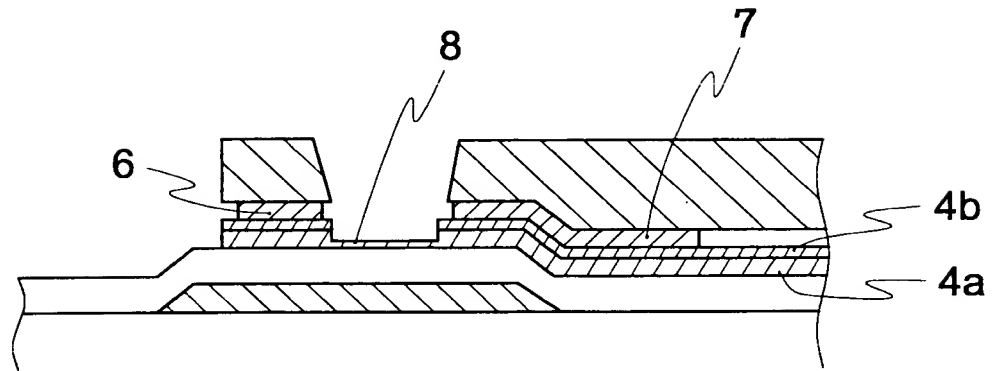


FIG. 13

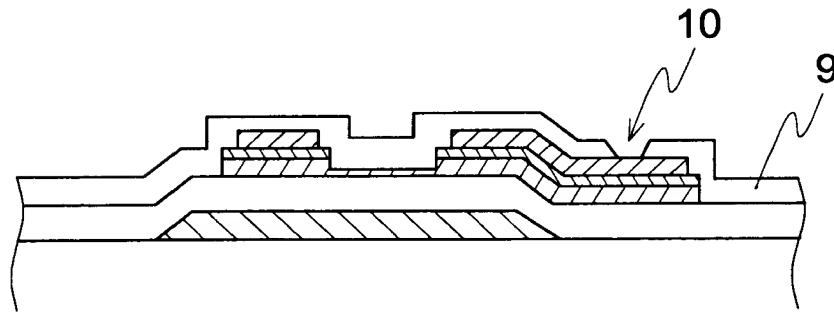


FIG. 14

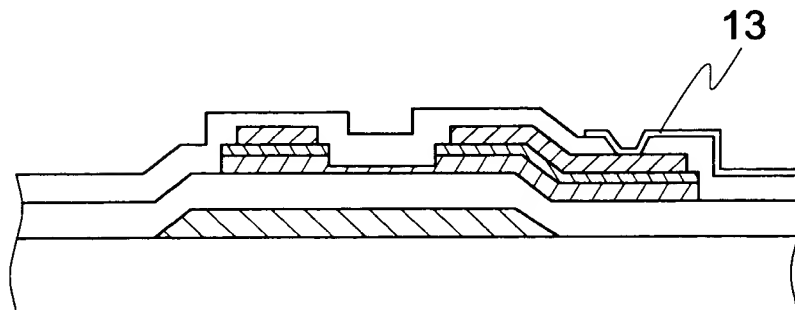




FIG. 9

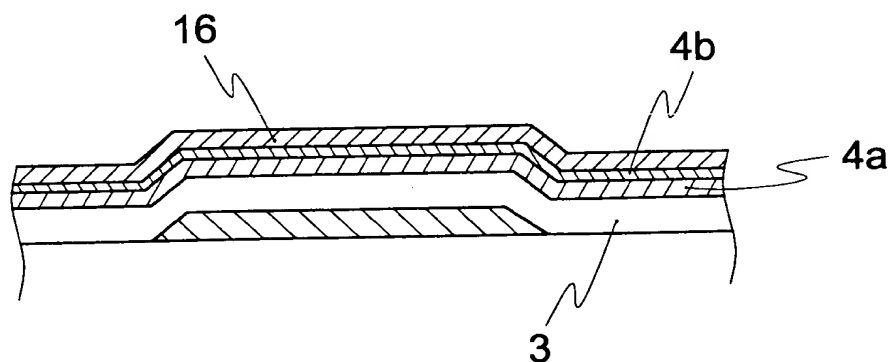


FIG. 10

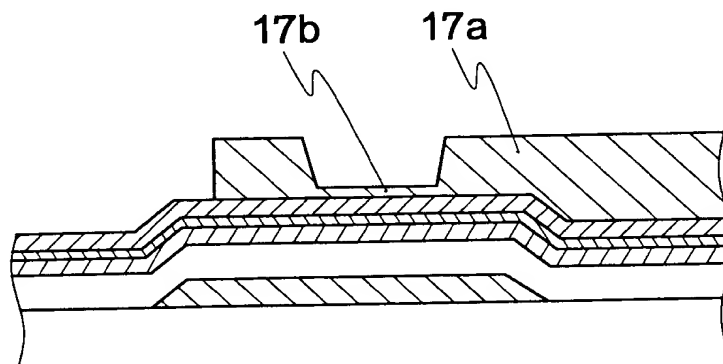


FIG. 11

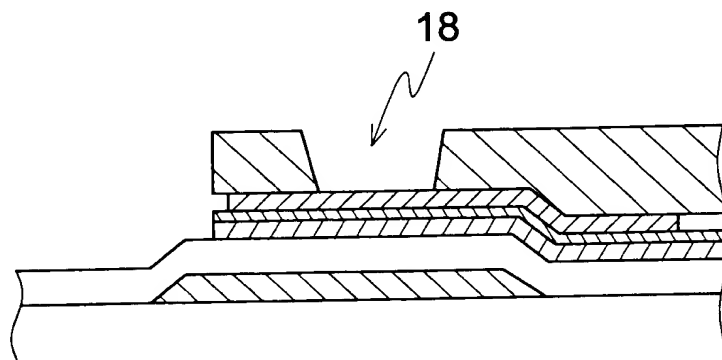


FIG. 15

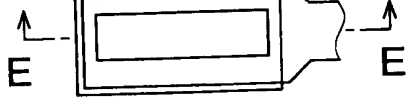


FIG. 16

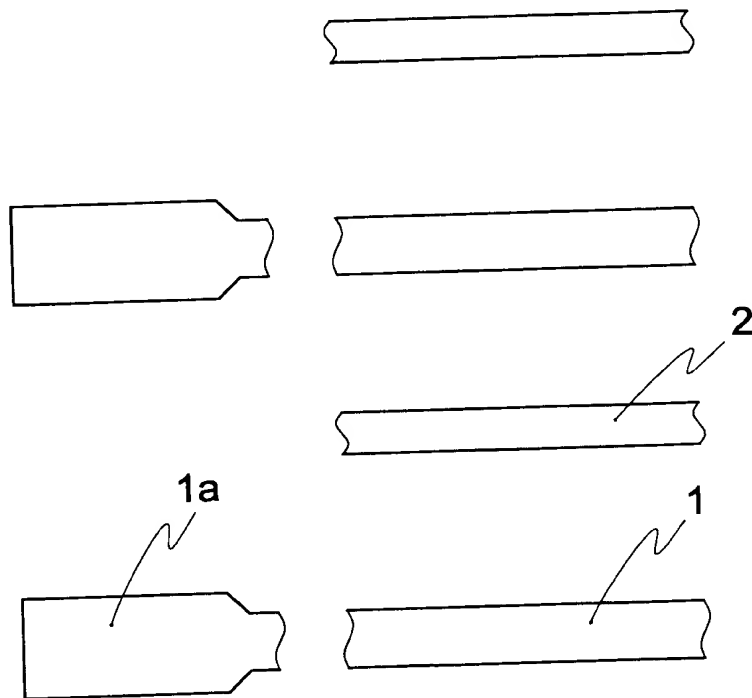


FIG. 17

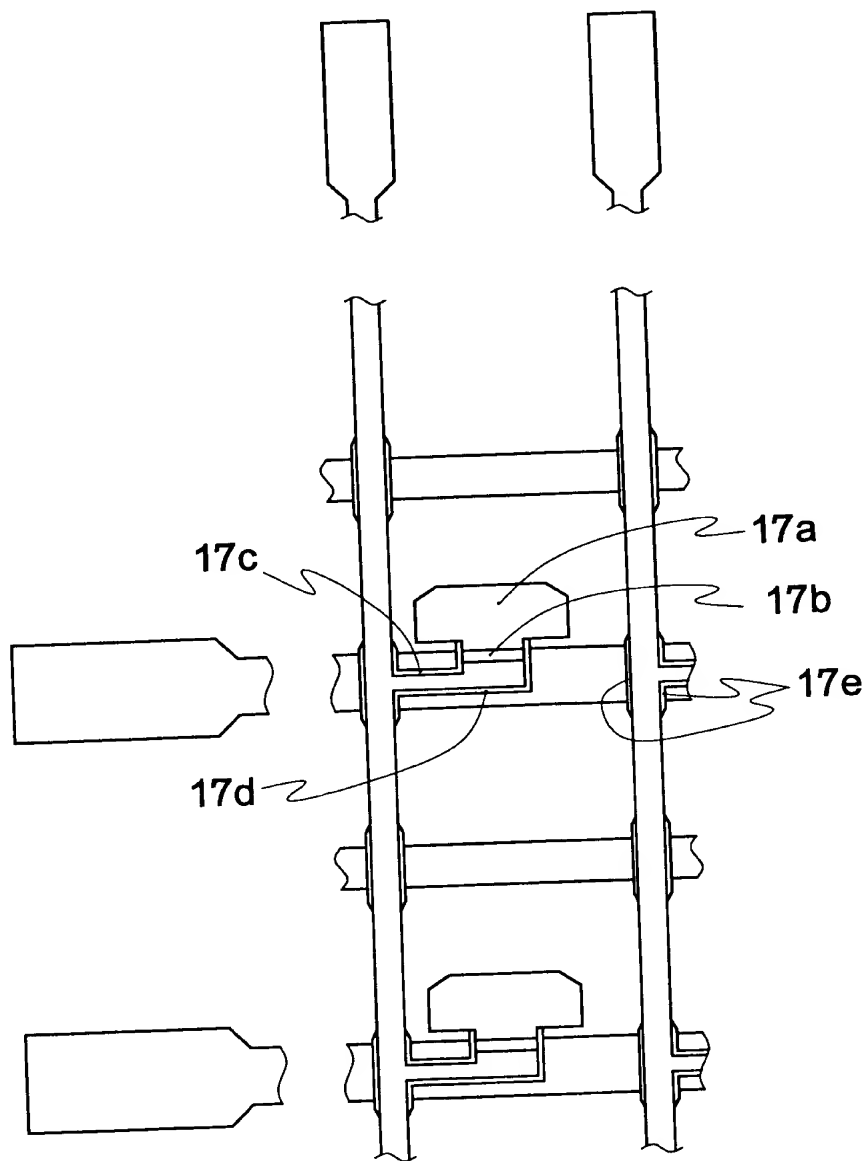


FIG. 18

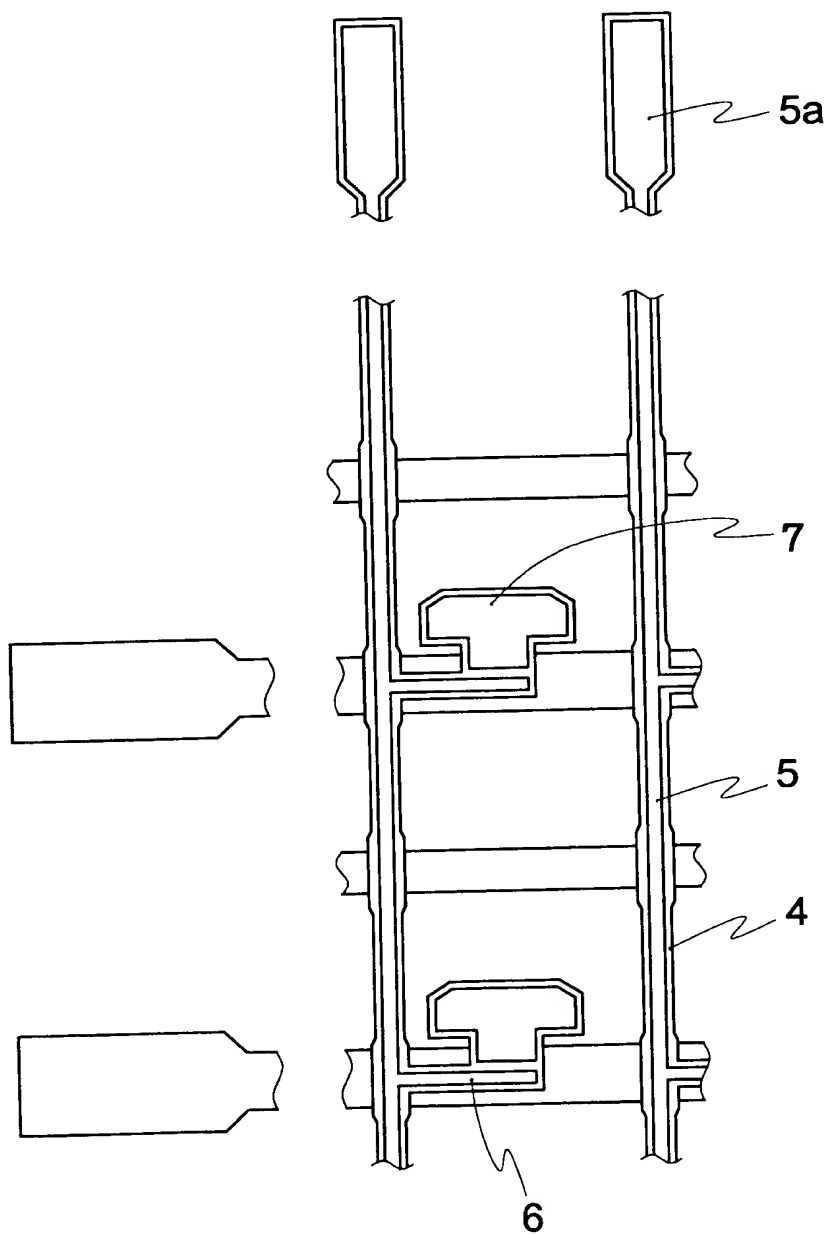


FIG. 19

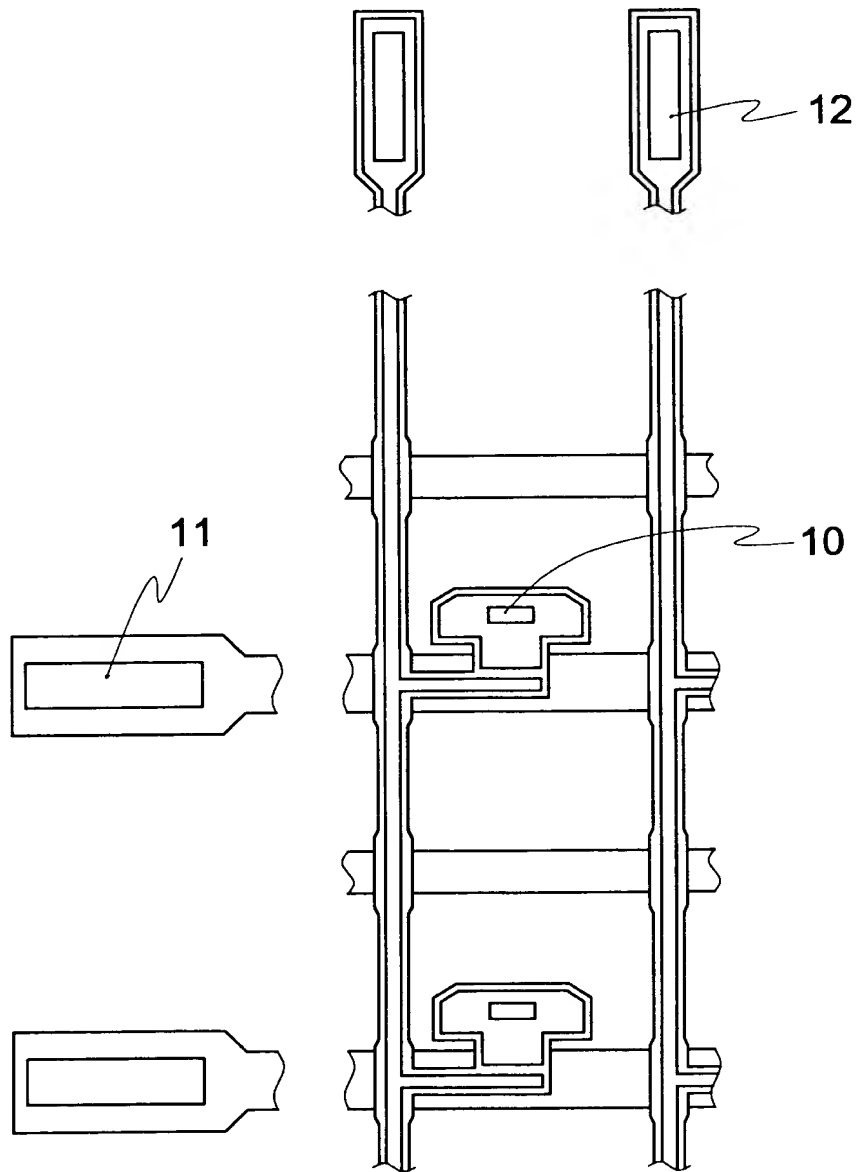


FIG. 20

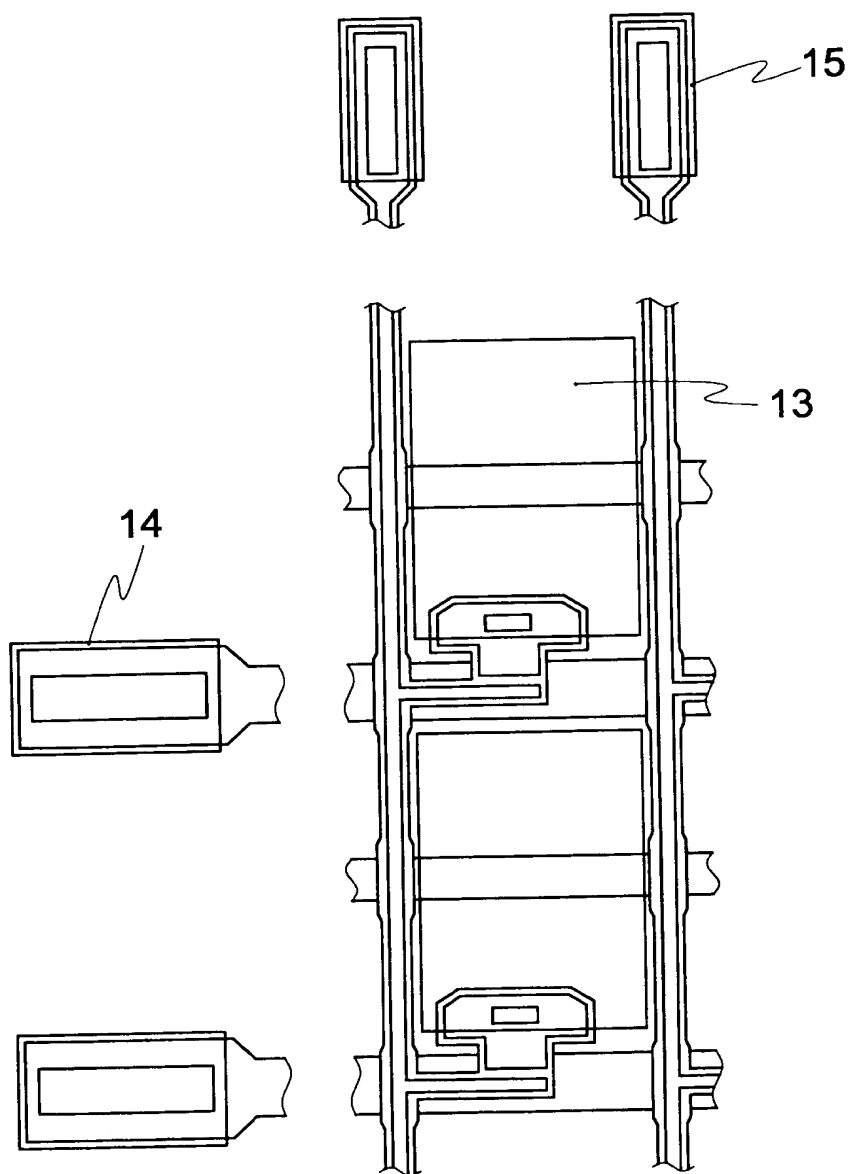


FIG. 21

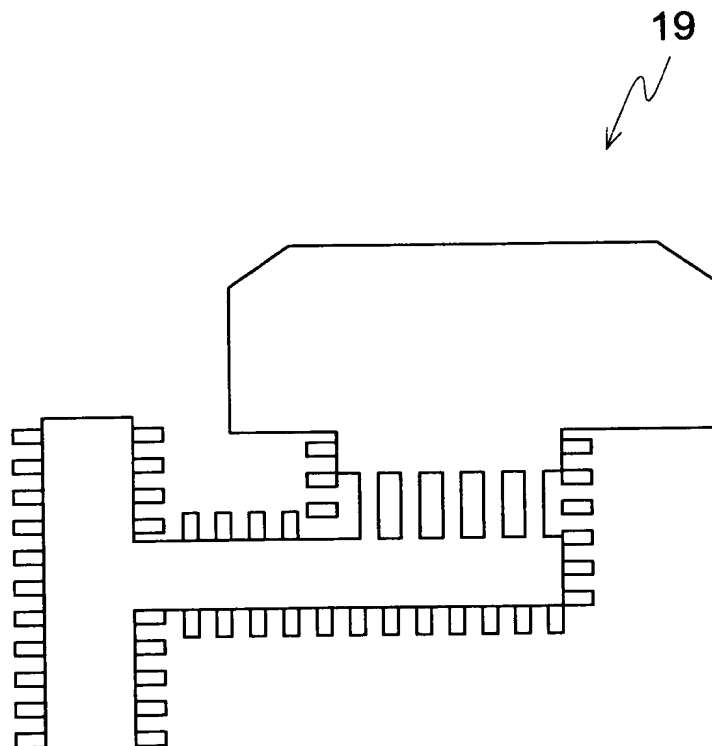




FIG. 22

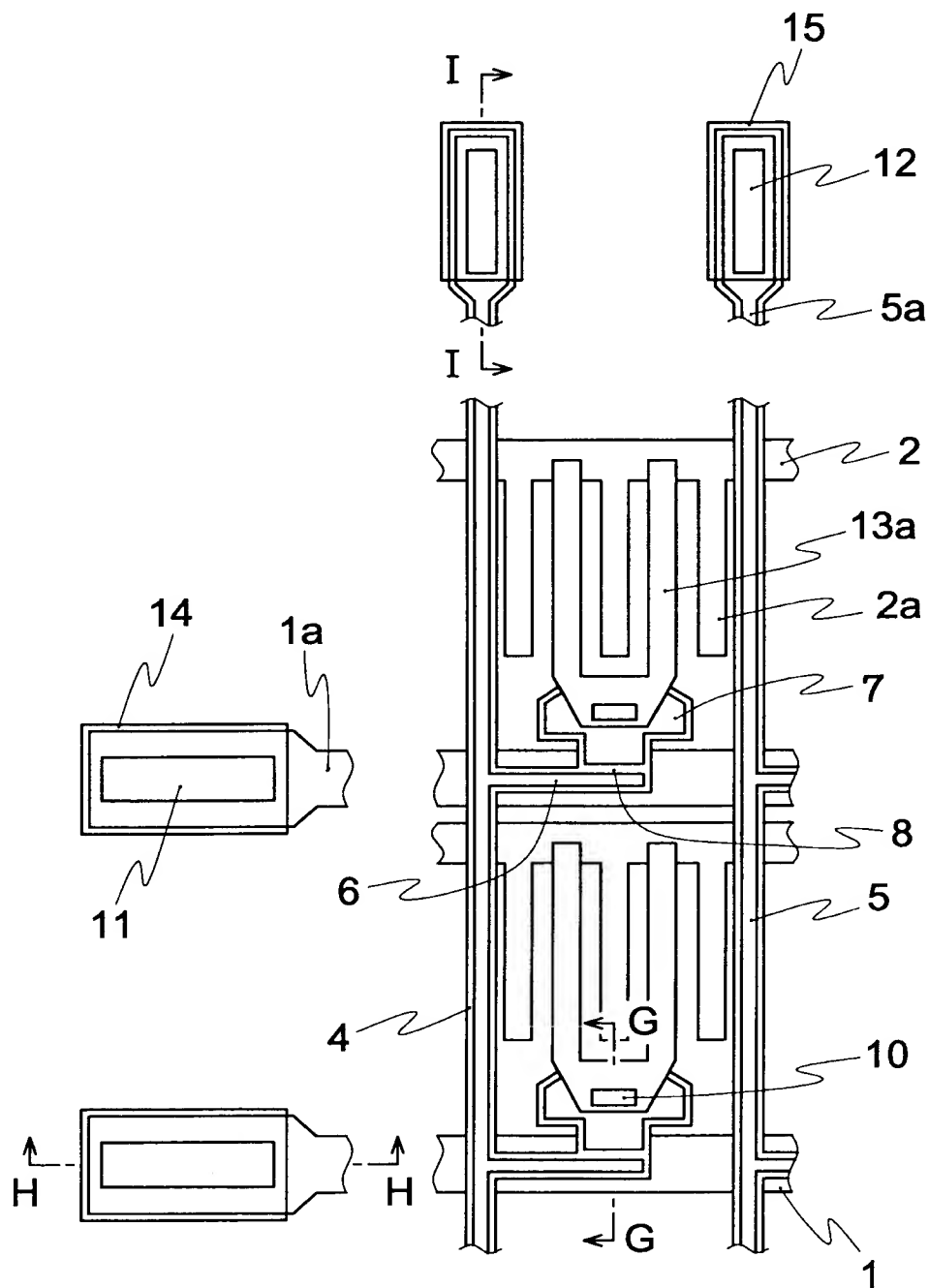


FIG. 23

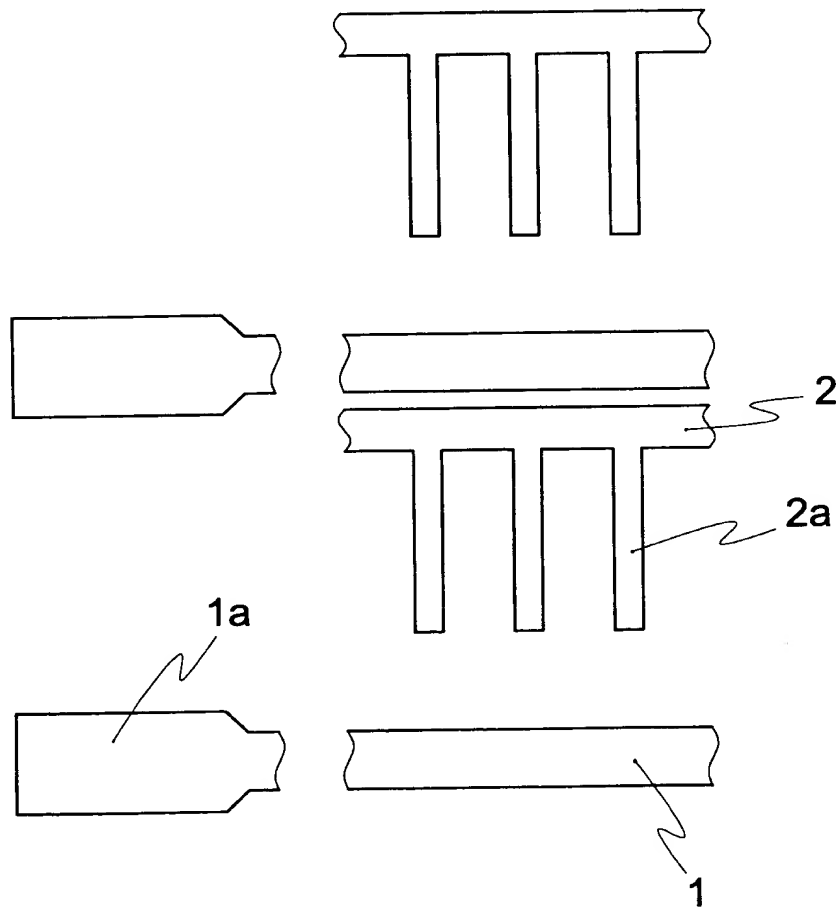


FIG. 24

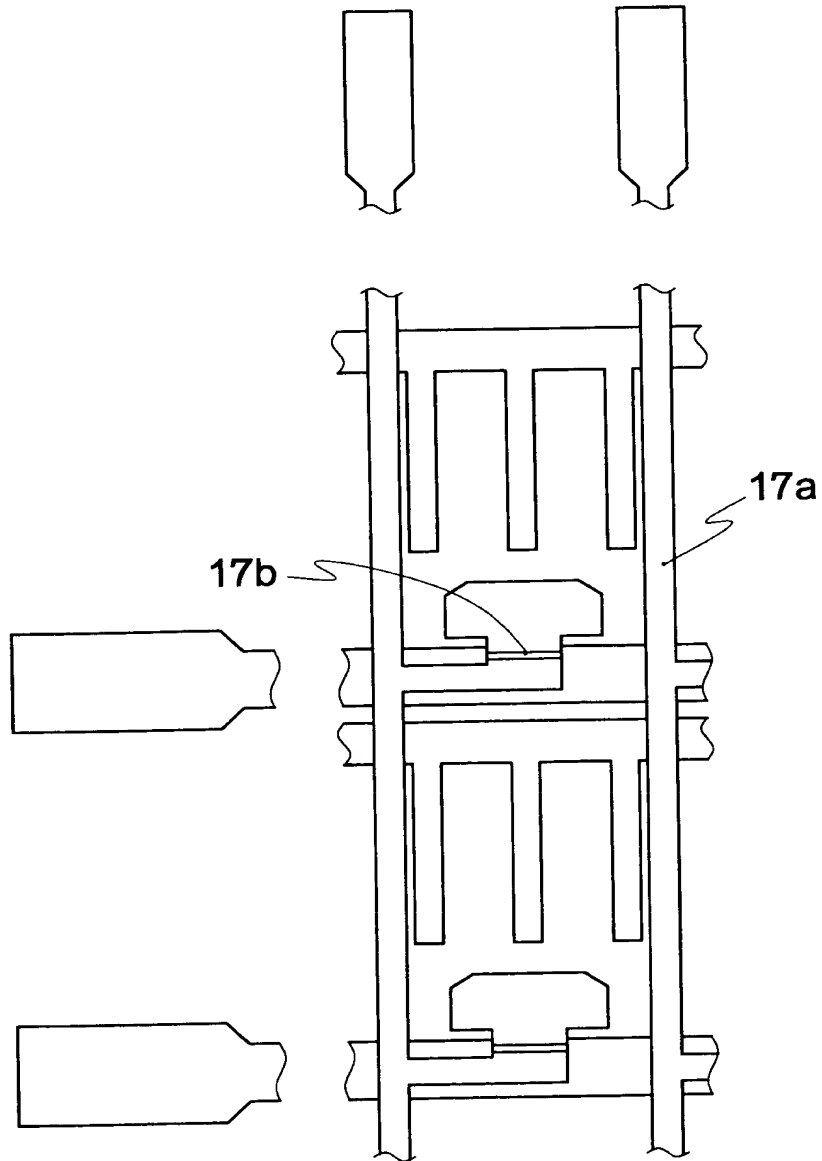


FIG. 25

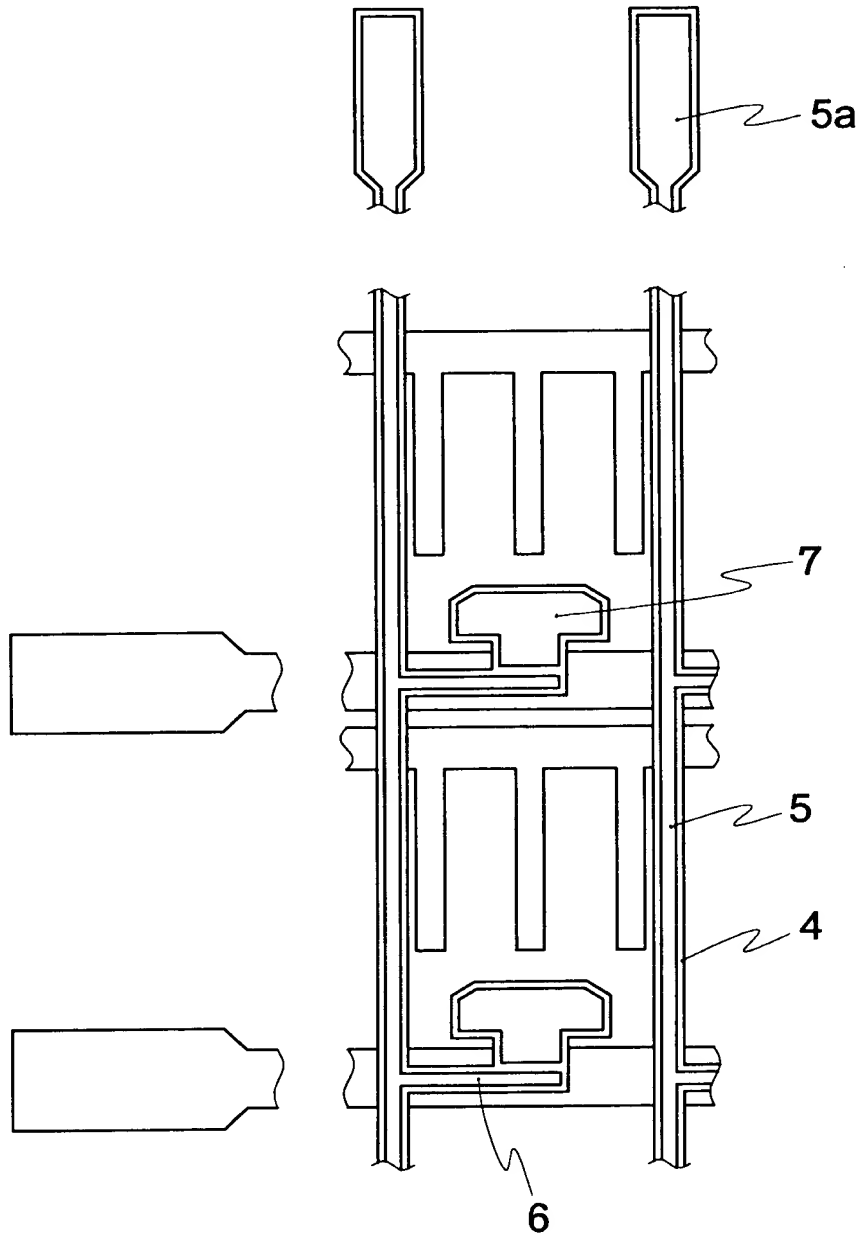


FIG. 26

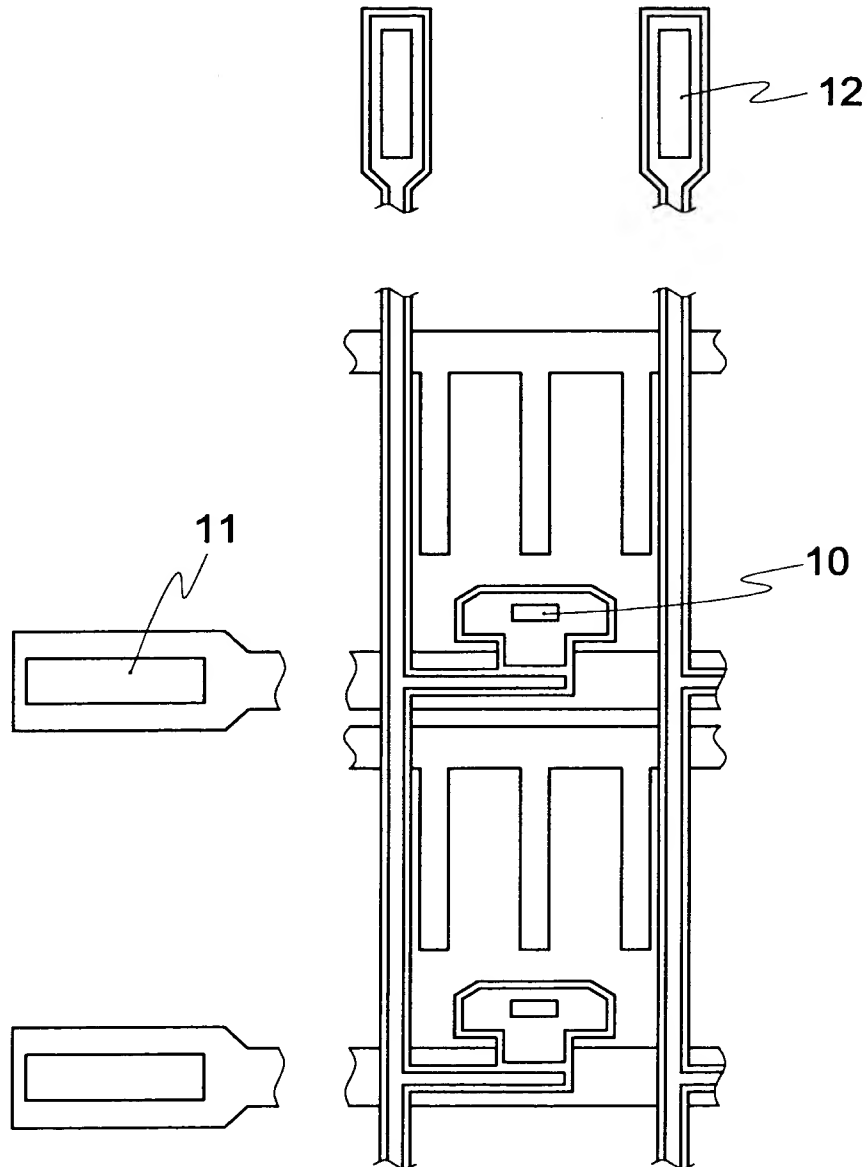


FIG. 27

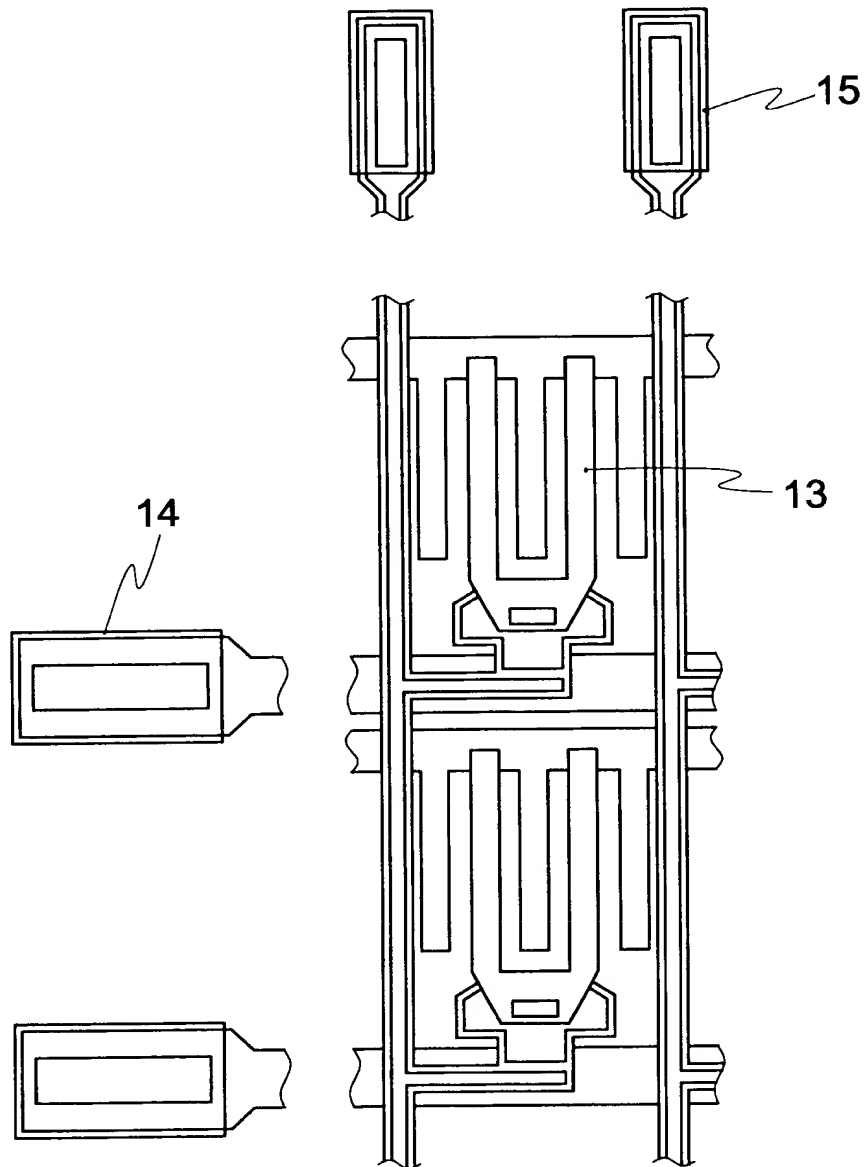


FIG. 28

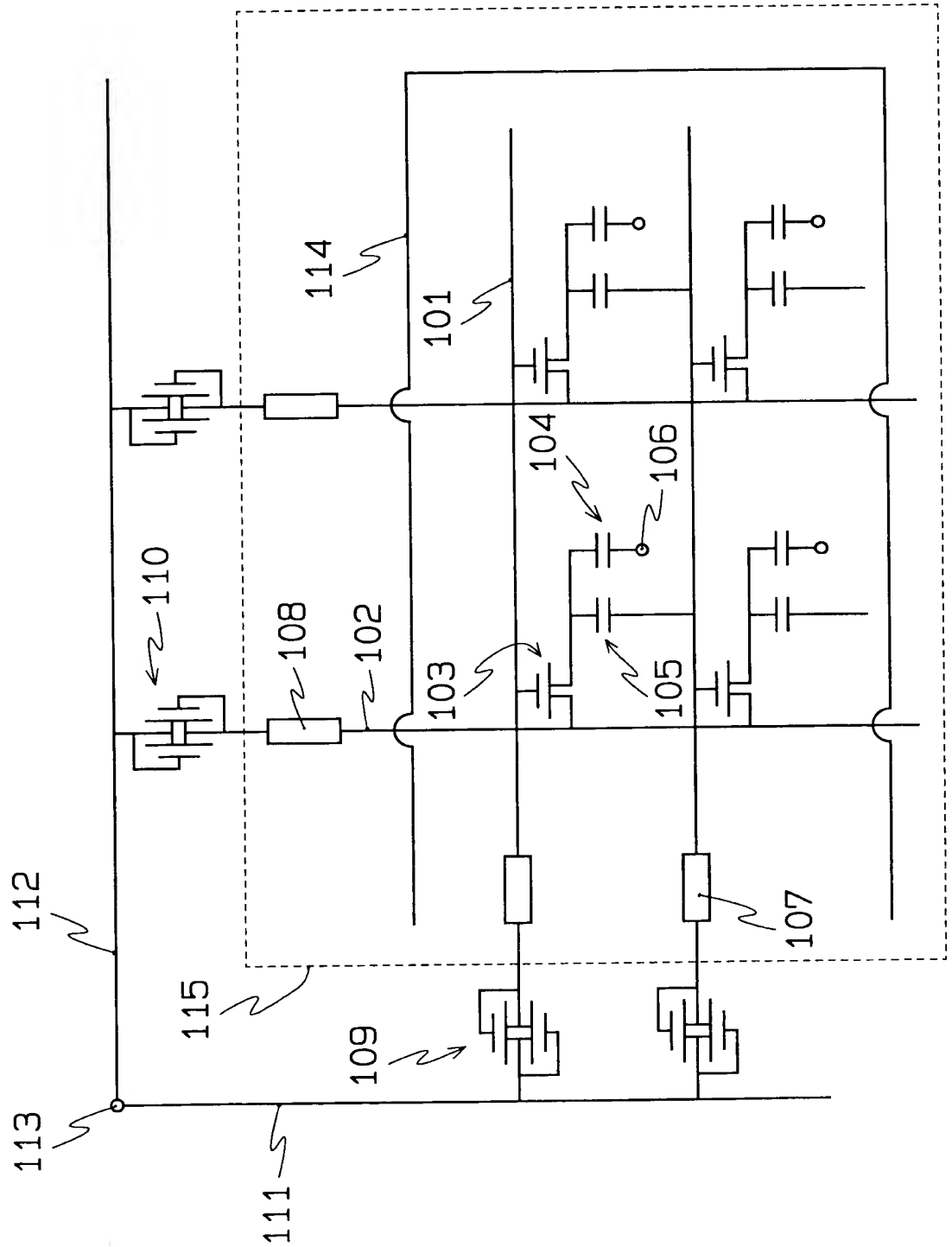


FIG. 29(a)

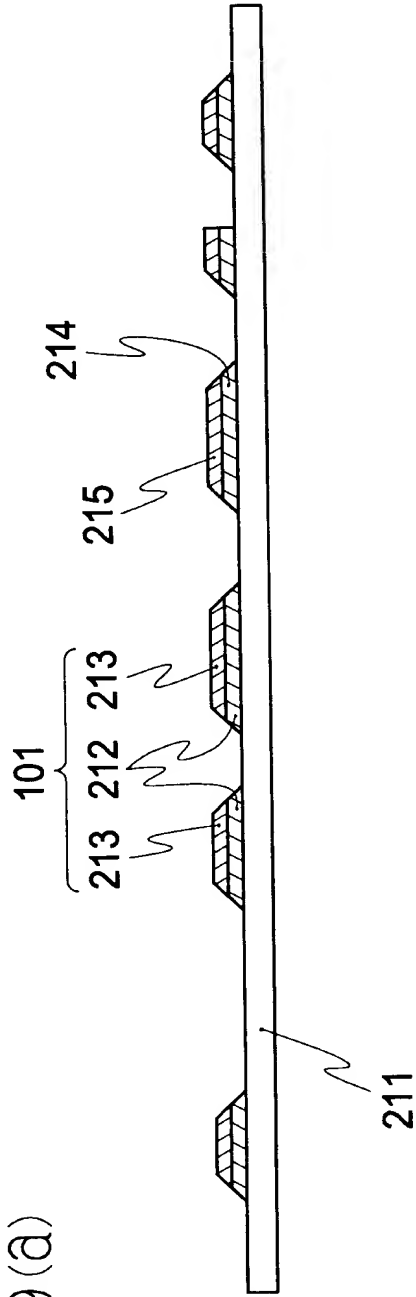


FIG. 29(b)

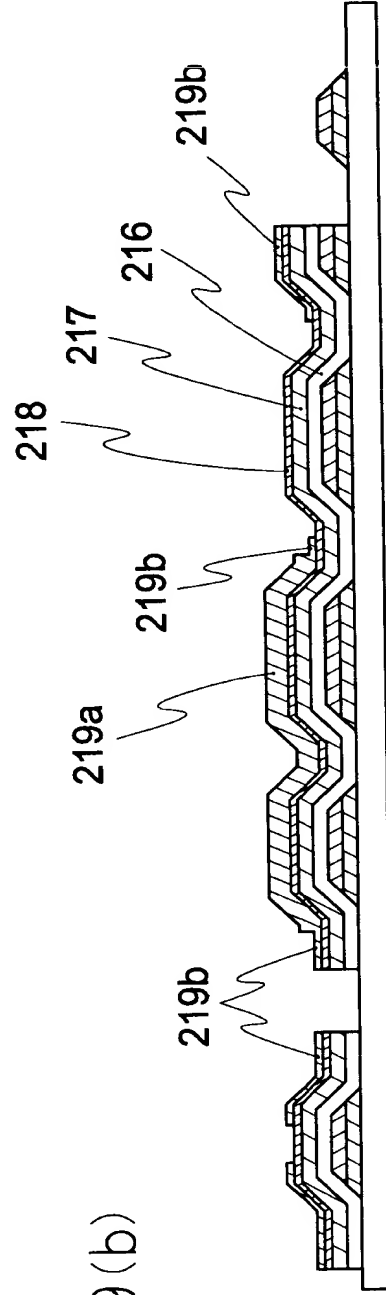




FIG. 30(a)

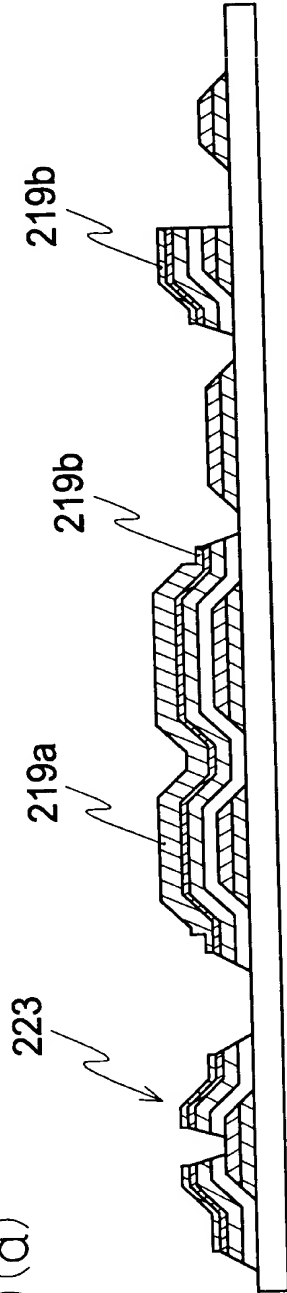


FIG. 30(b)

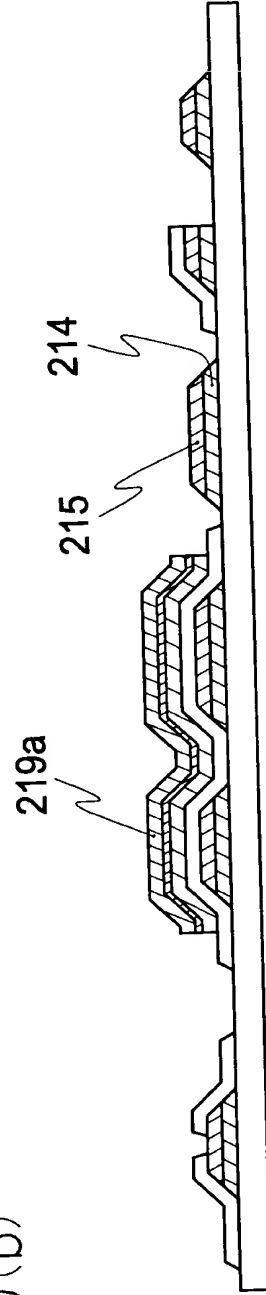


FIG. 31(a)

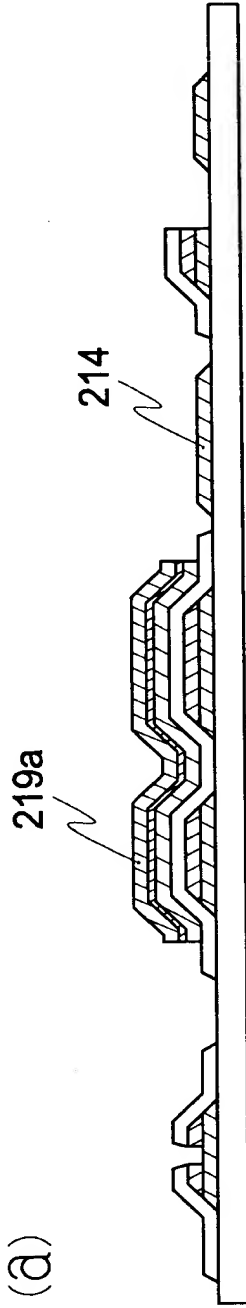


FIG. 31(b)

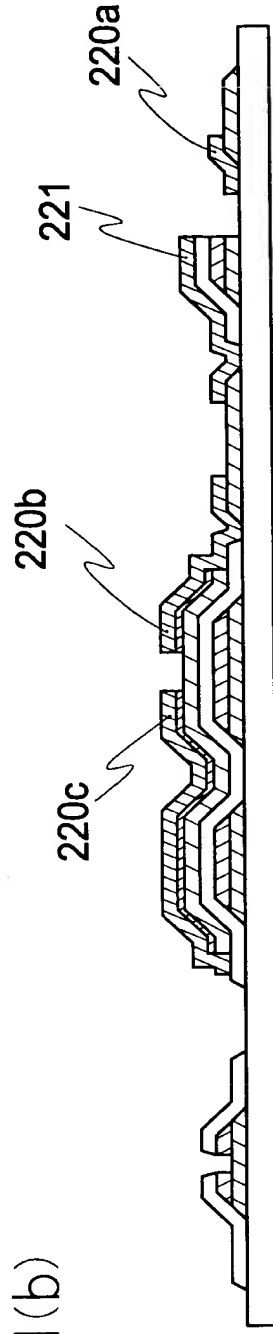


FIG. 31(c)

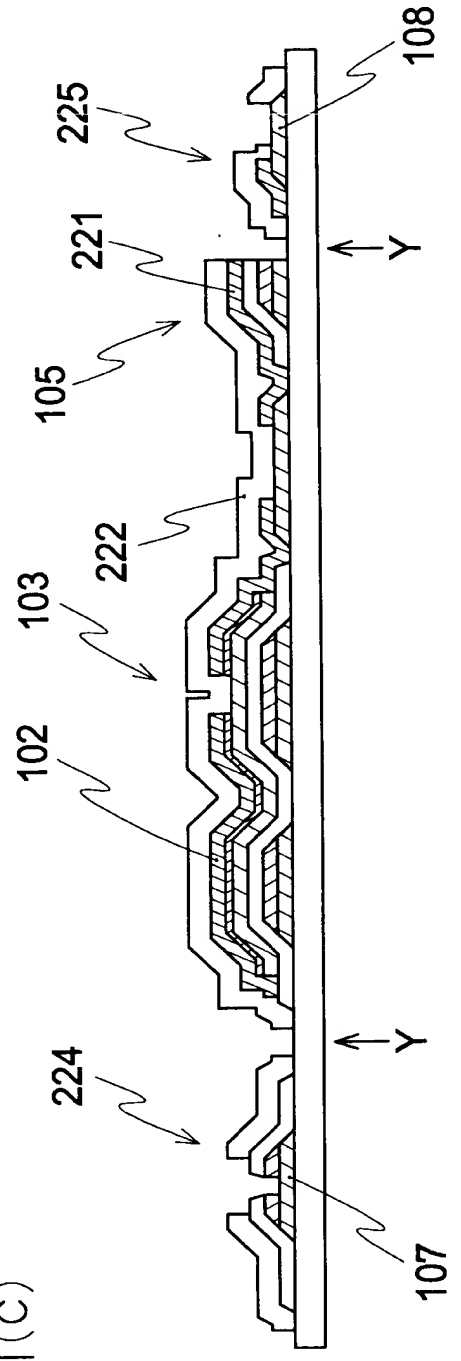


FIG. 32(a)

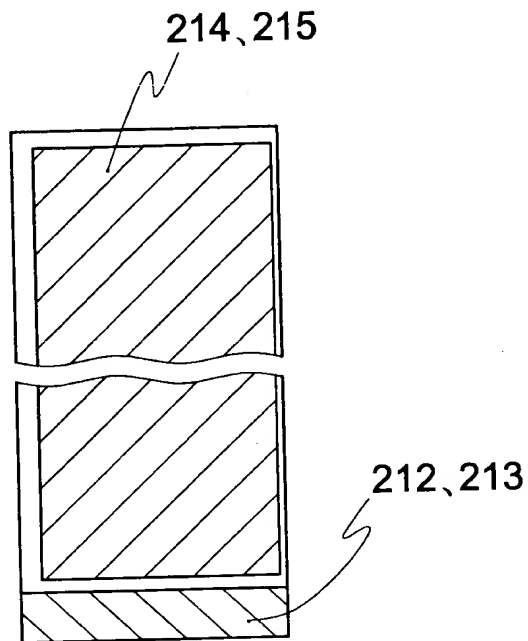


FIG. 32(b)

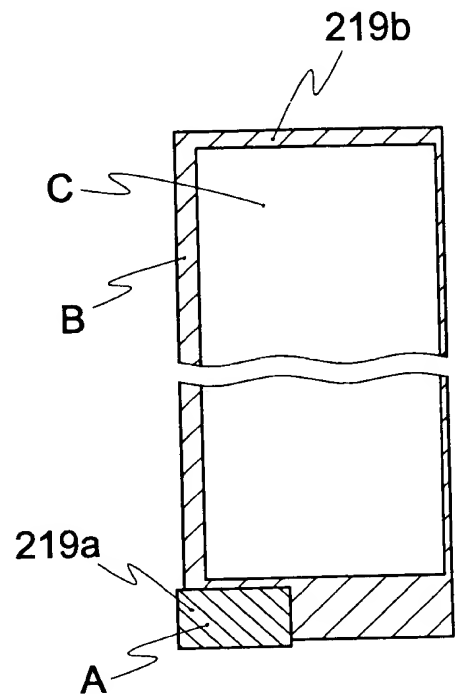


FIG. 32(c)

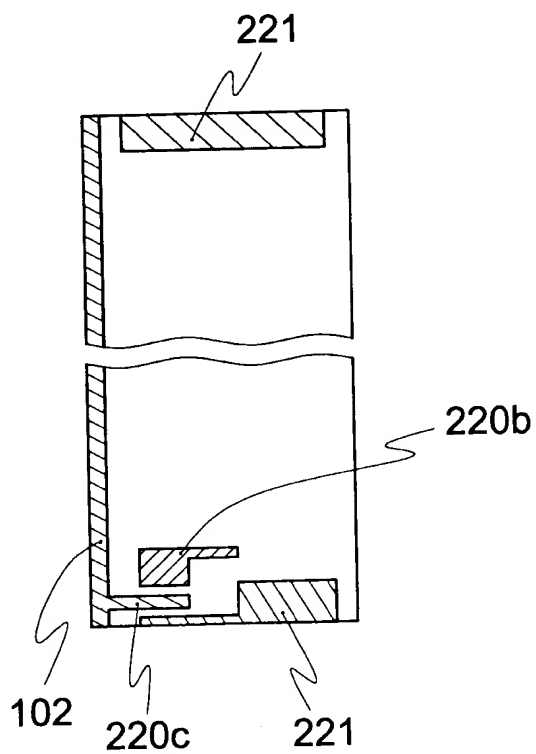


FIG. 32(d)

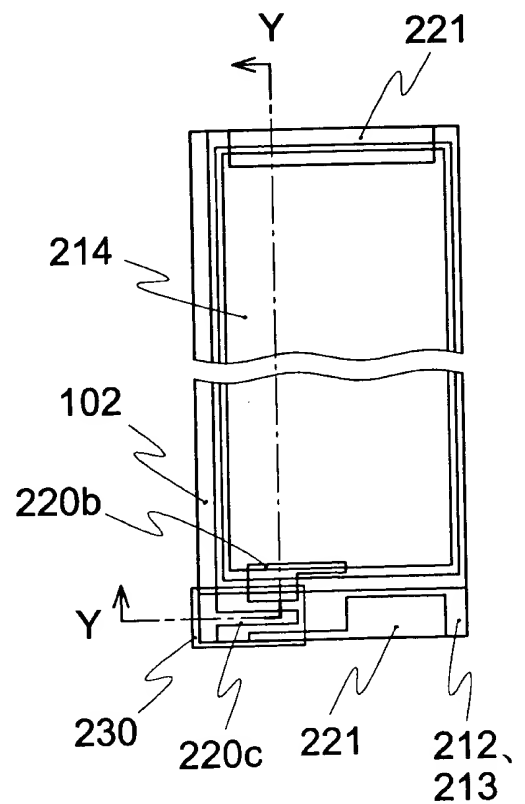


FIG. 33

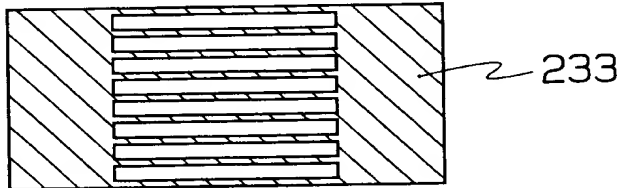


FIG. 34

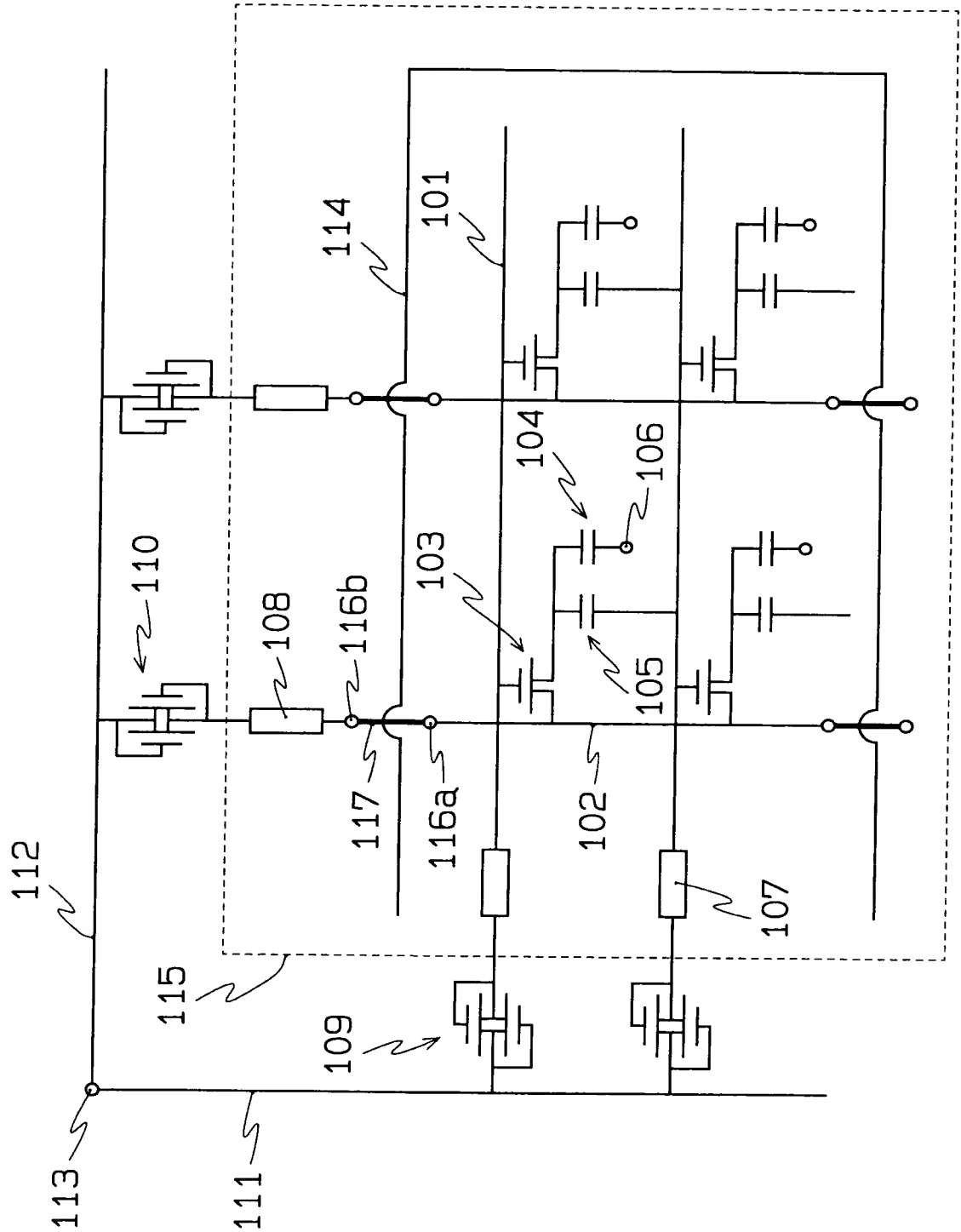


FIG. 35

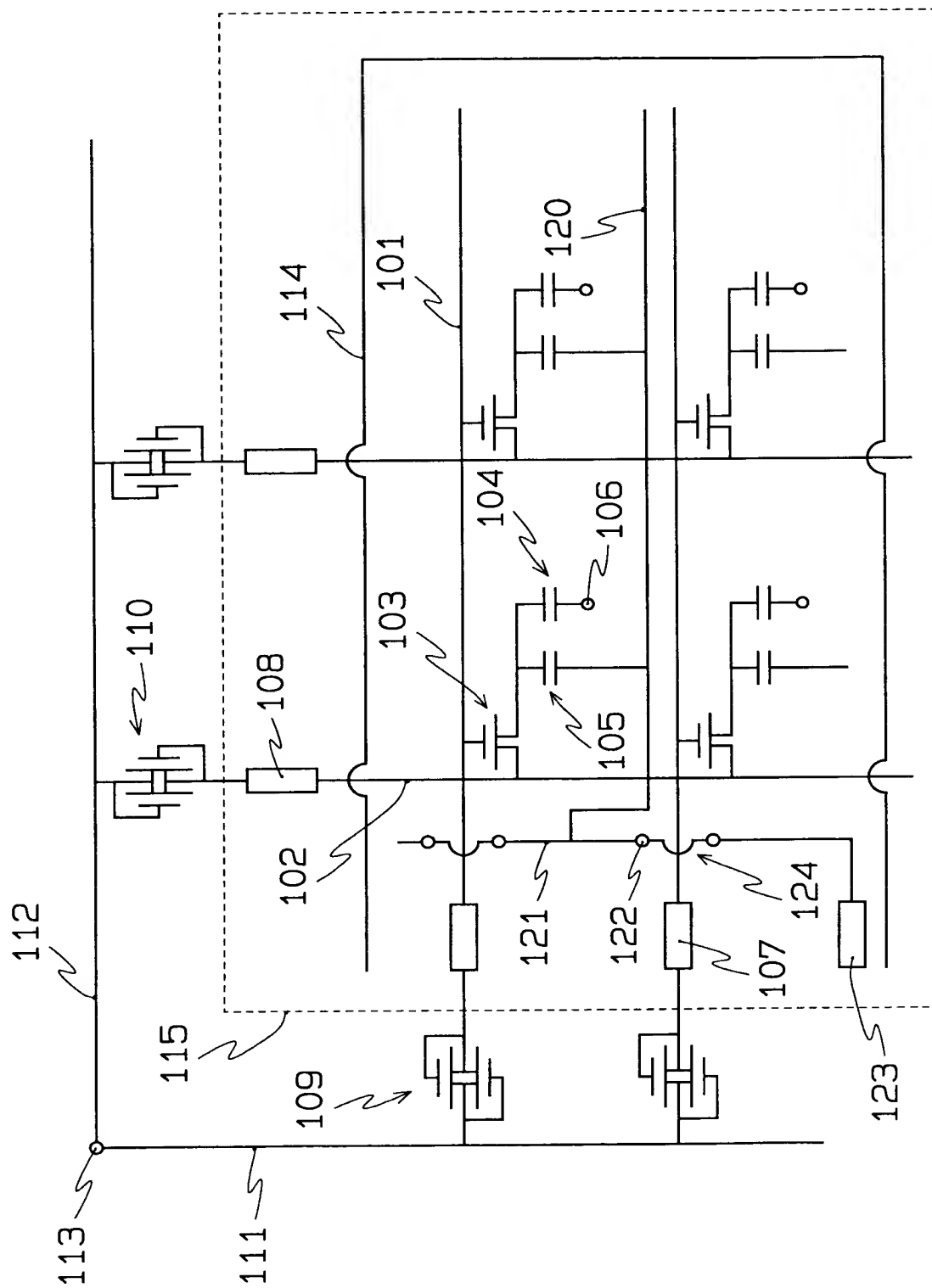


FIG. 36

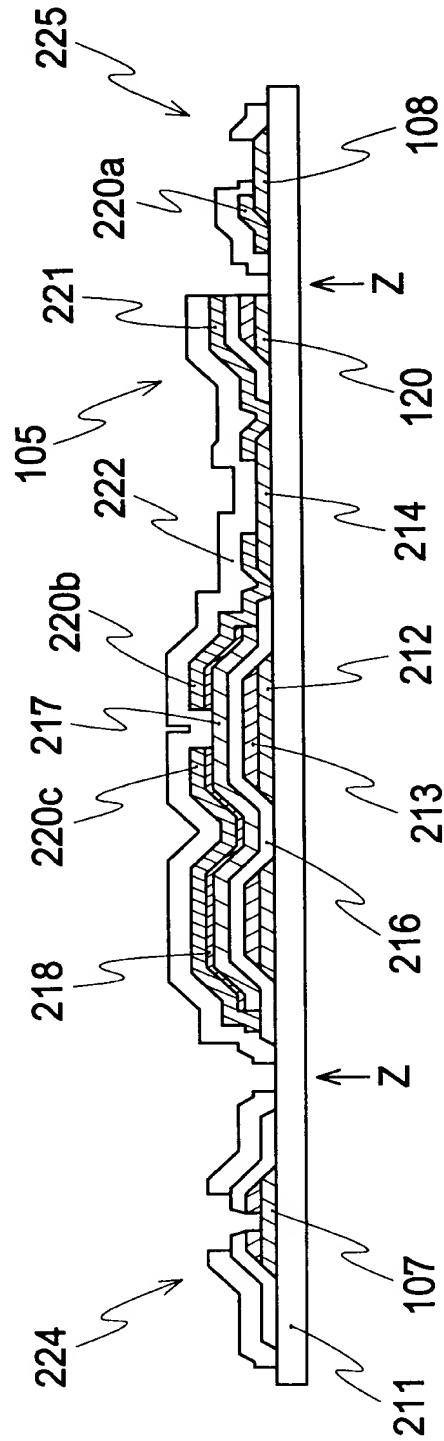


FIG. 37(a)

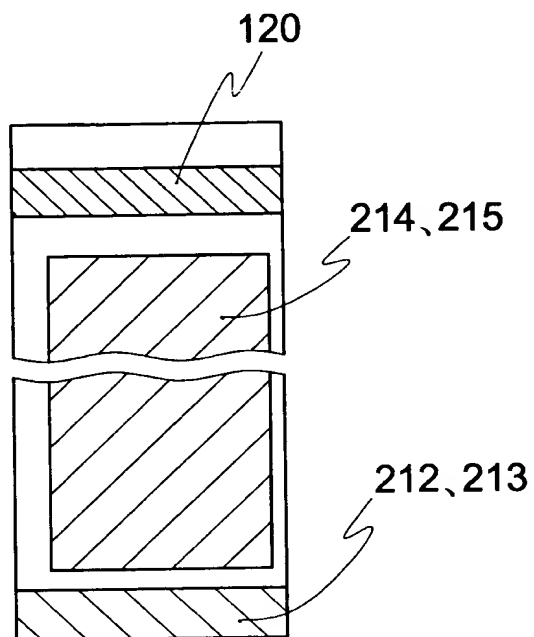


FIG. 37(b)

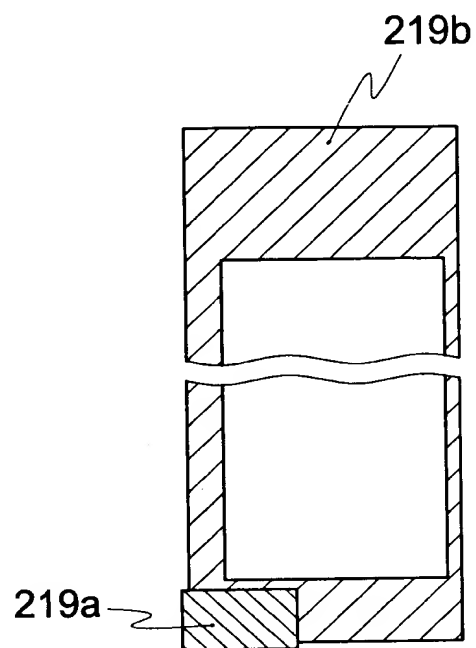


FIG. 37(c)

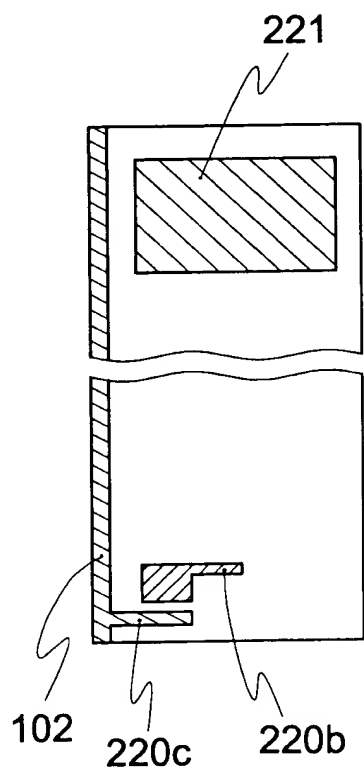


FIG. 37(d)

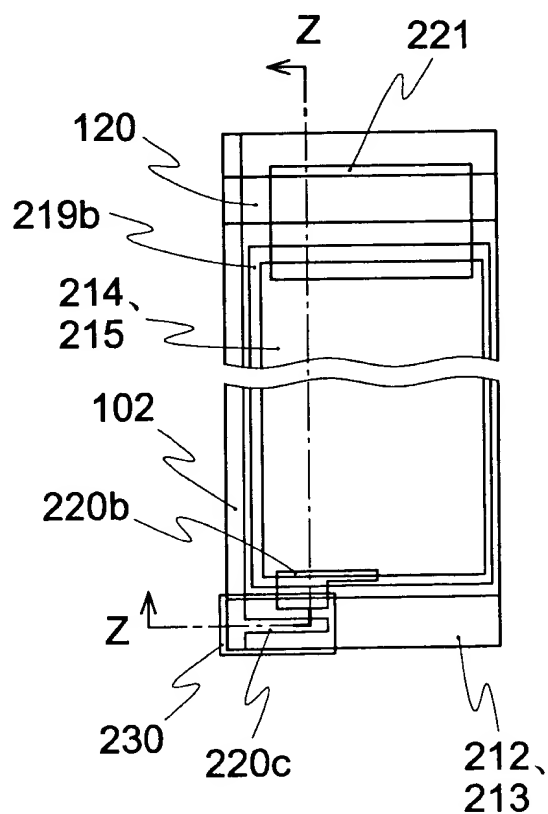




FIG. 38

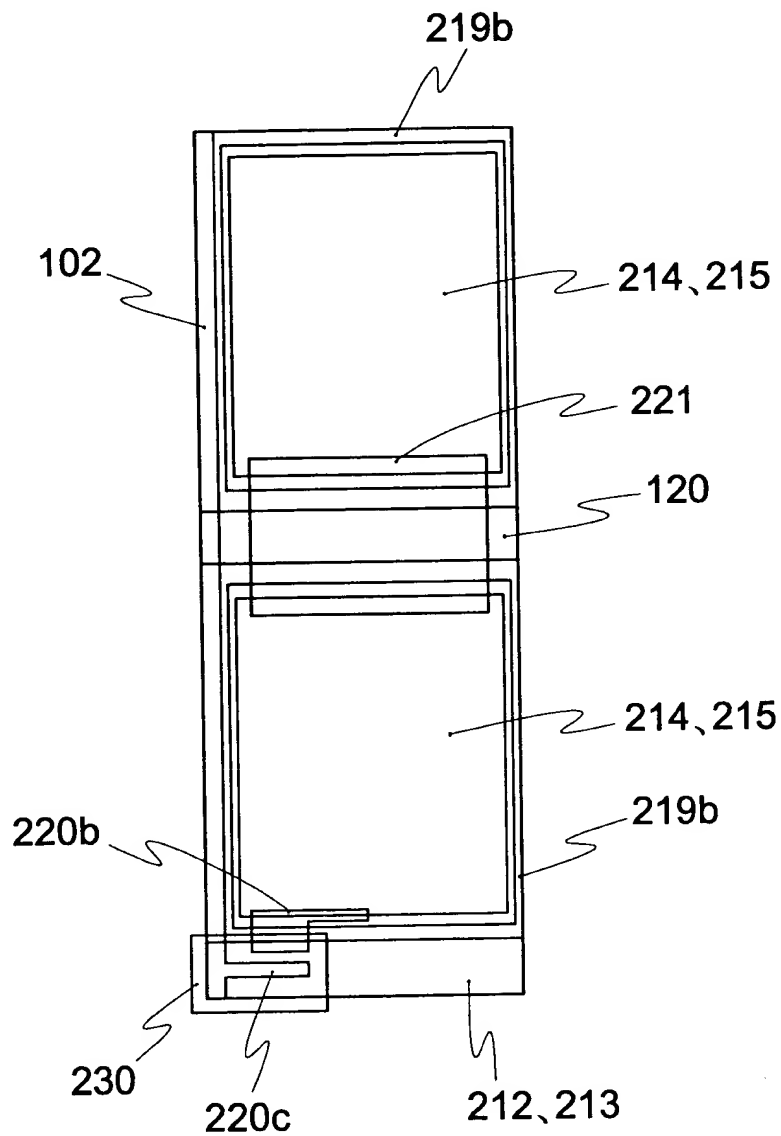


FIG. 39

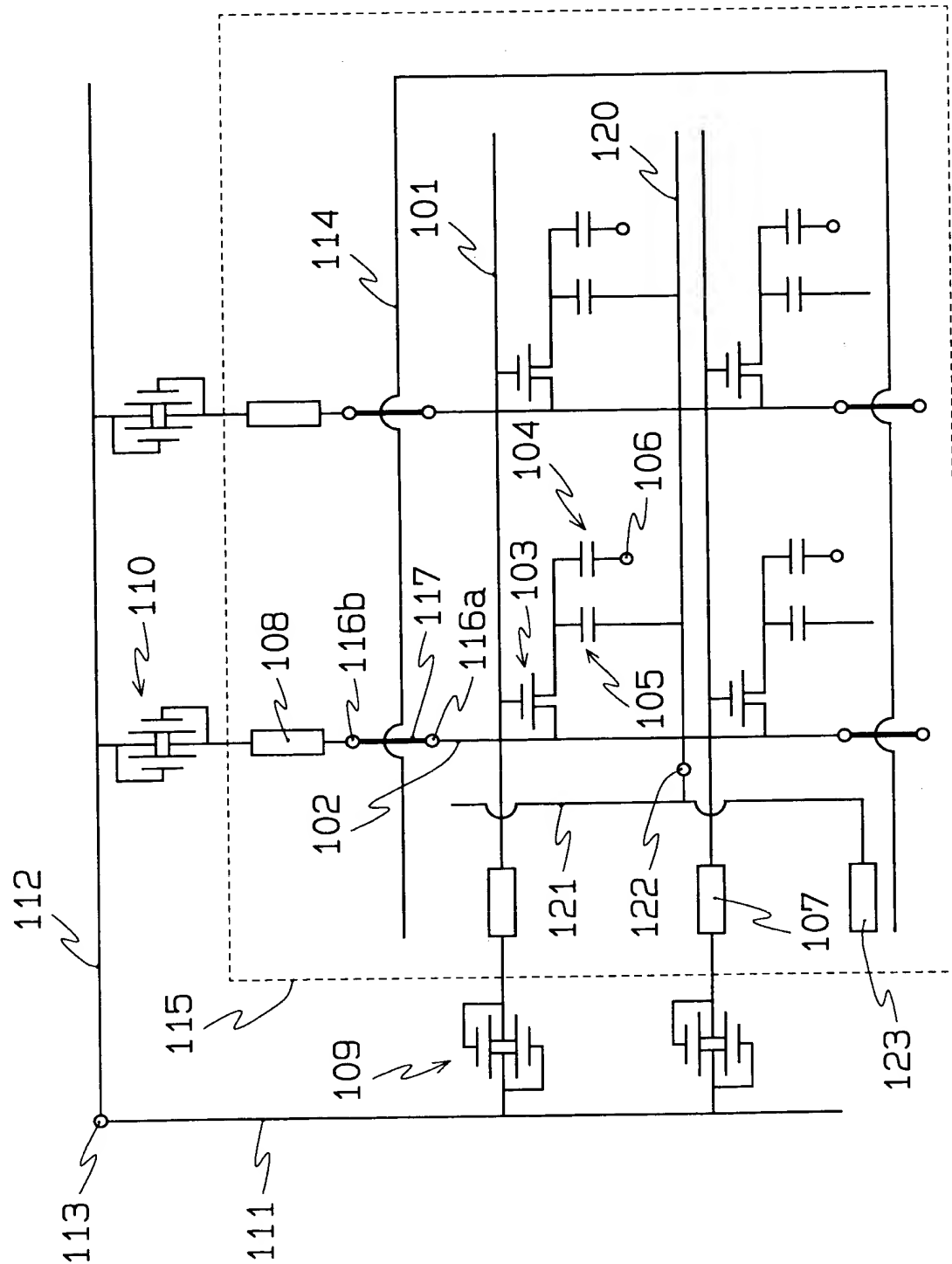


FIG. 40

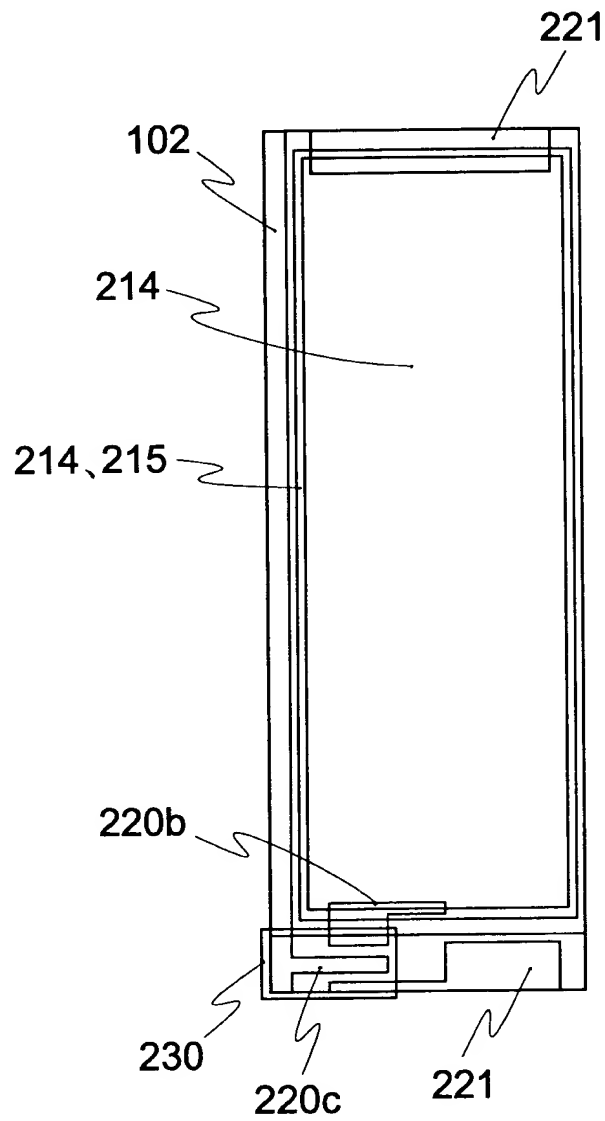


FIG. 41(a)

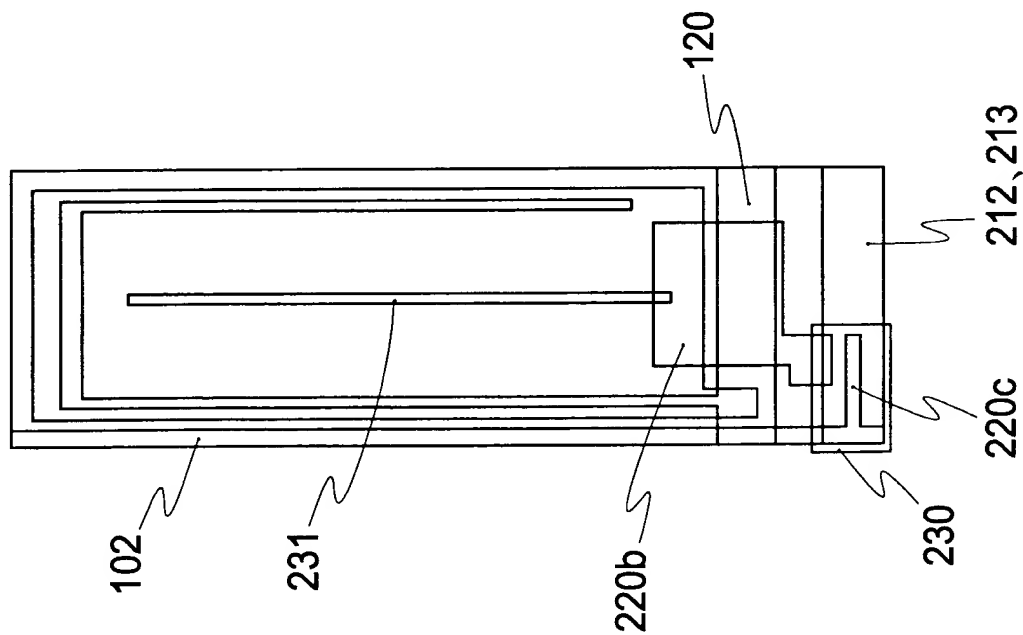


FIG. 41(b)

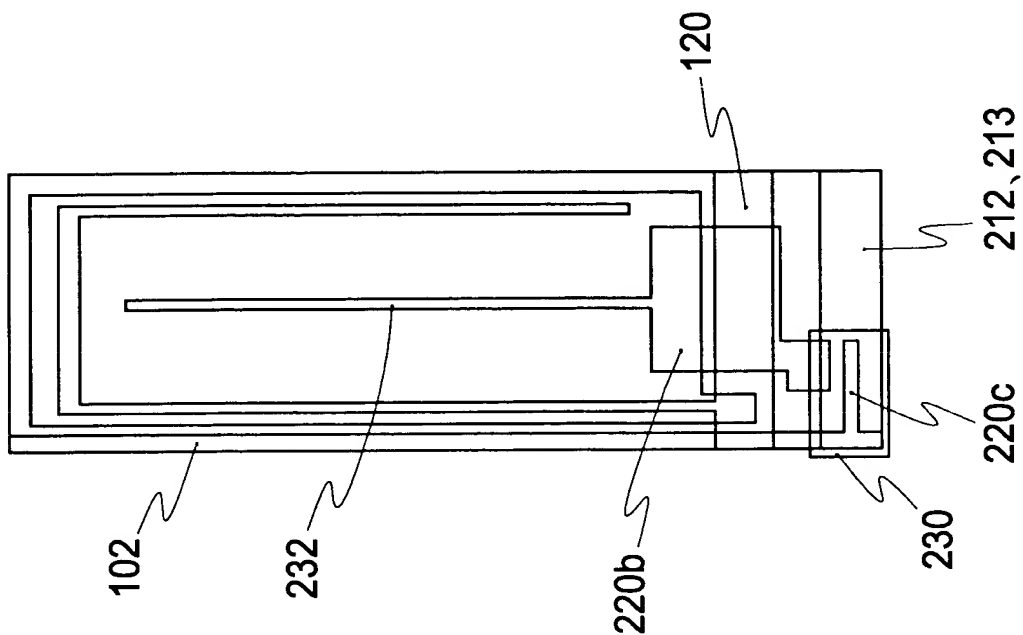


FIG. 42(a)

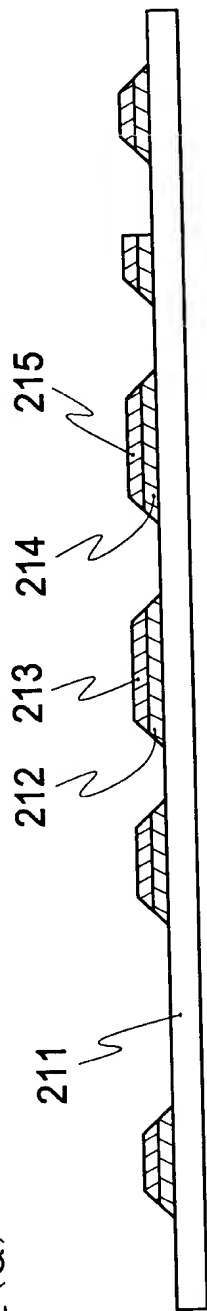


FIG. 42(b)

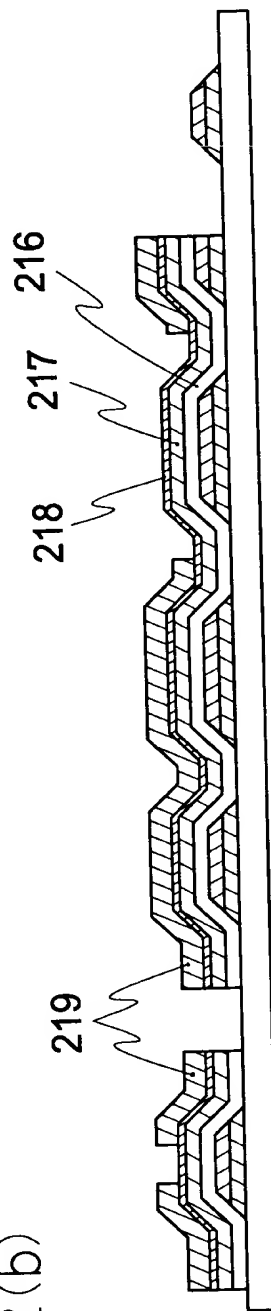


FIG. 42(c)

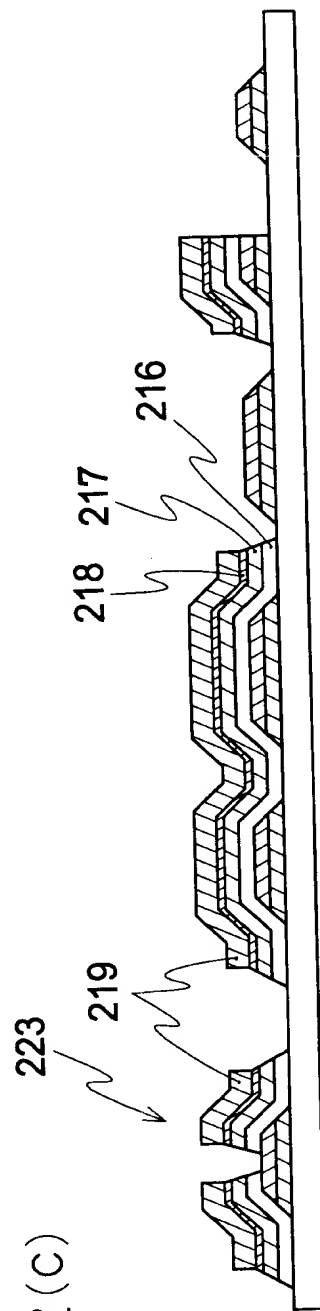


FIG. 43(a)

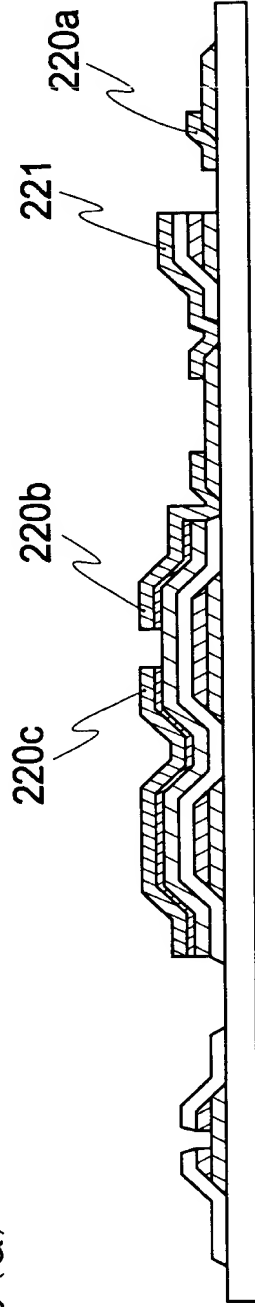
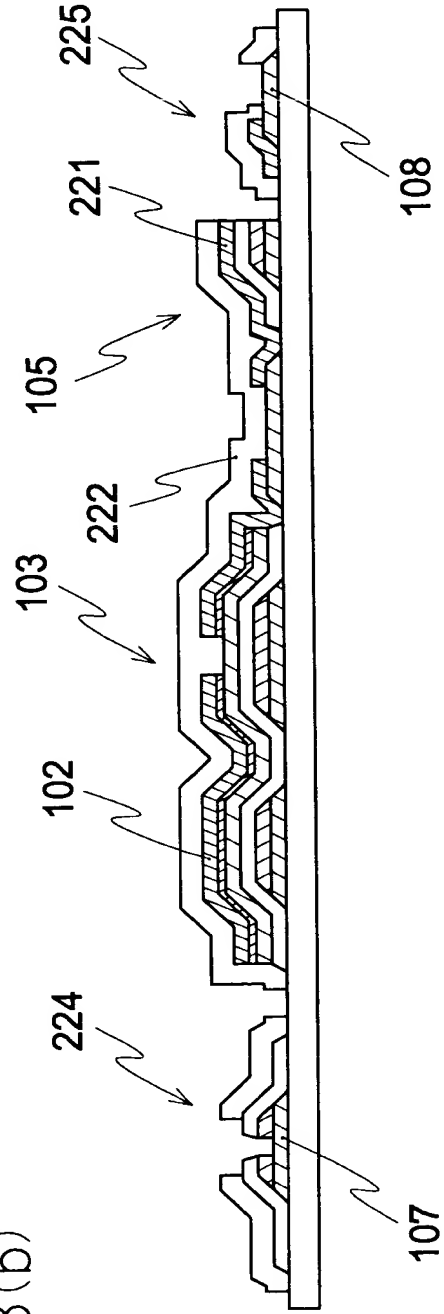


FIG. 43(b)



A cross-sectional view of a substrate 410. A series of protrusions 411 are formed on the top surface of the substrate. A specific protrusion is labeled 412.

A cross-sectional view of a semiconductor device. A substrate 423 is shown at the bottom. On top of the substrate, there is a patterned layer 418a. The layer 418a consists of several rectangular blocks separated by gaps. The blocks have a stepped top surface. The layer 418a is formed on a thin layer 418b, which is in turn formed on the substrate 423.

FIG. 45(a)

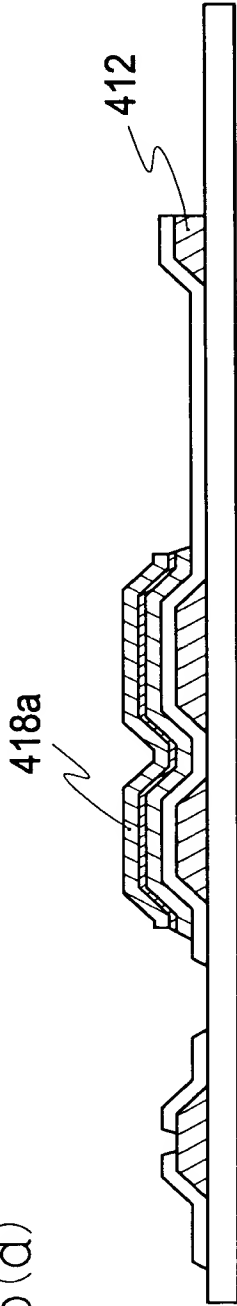


FIG. 45(b)

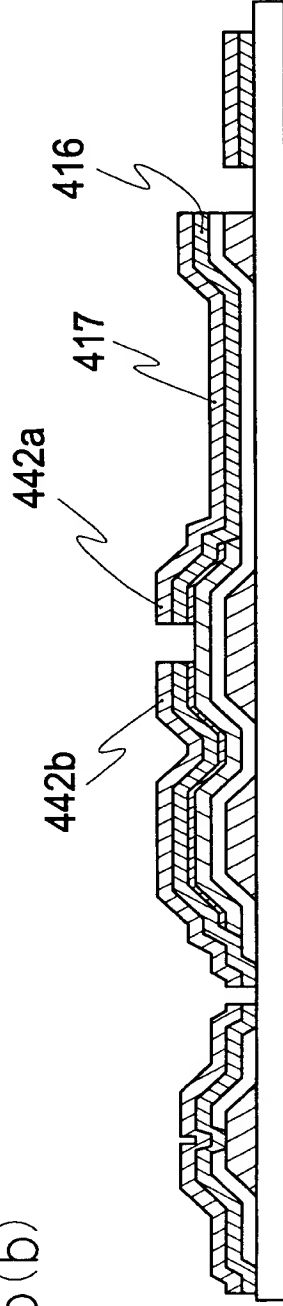


FIG. 45(c)

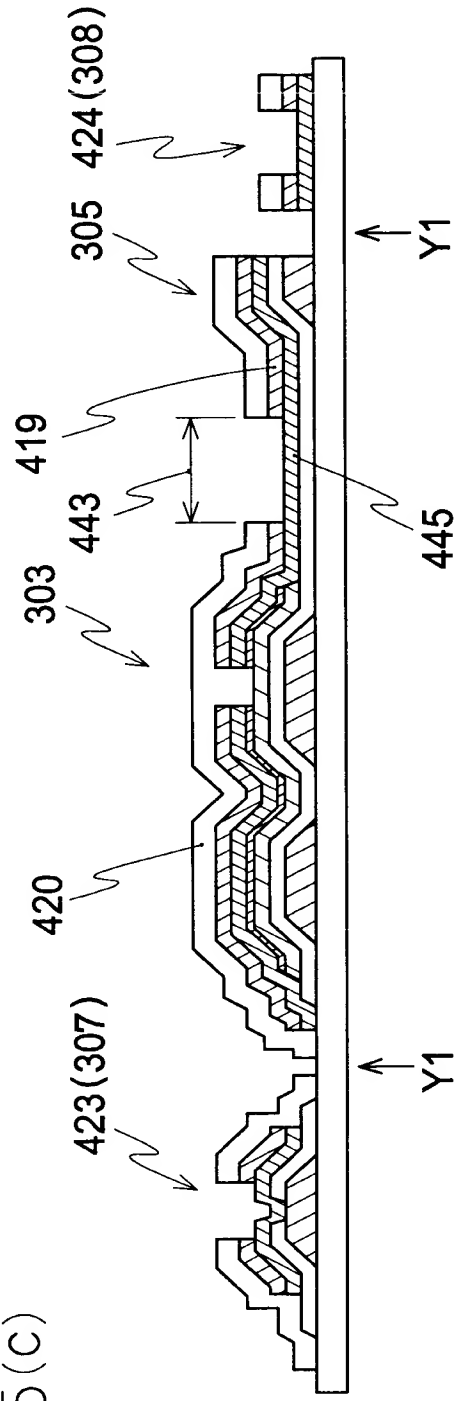




FIG. 46(a)

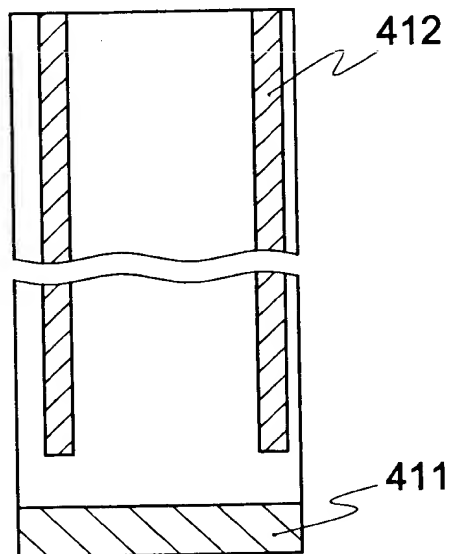


FIG. 46(b)

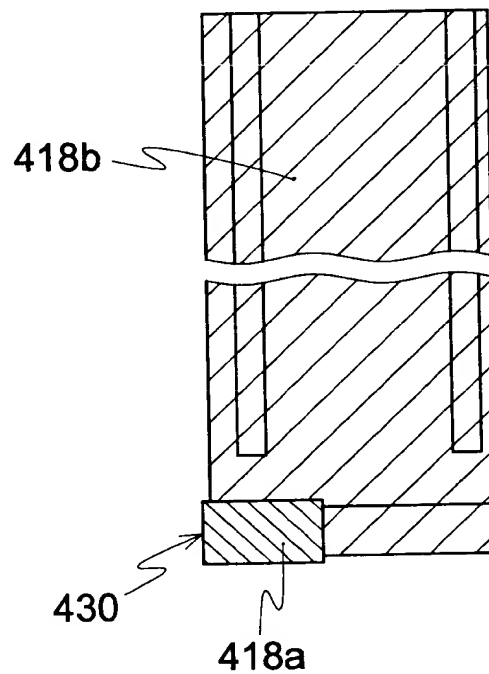


FIG. 46(c)

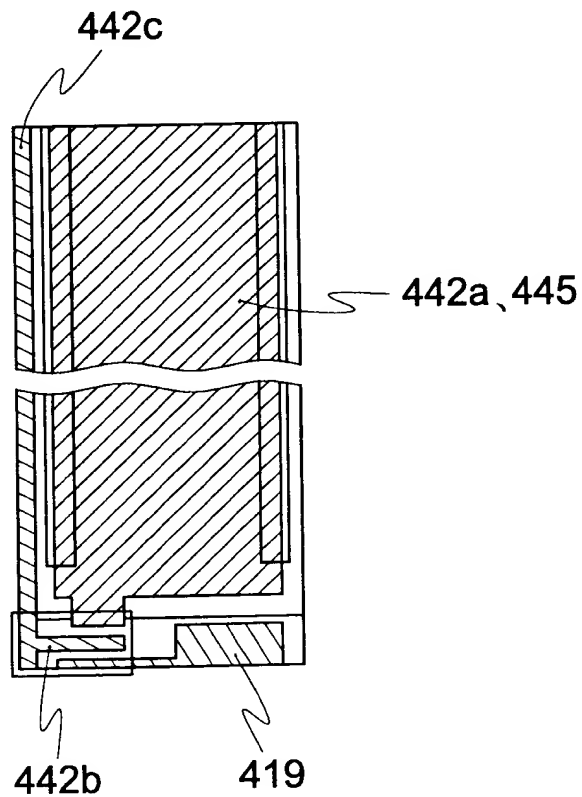


FIG. 47(a)

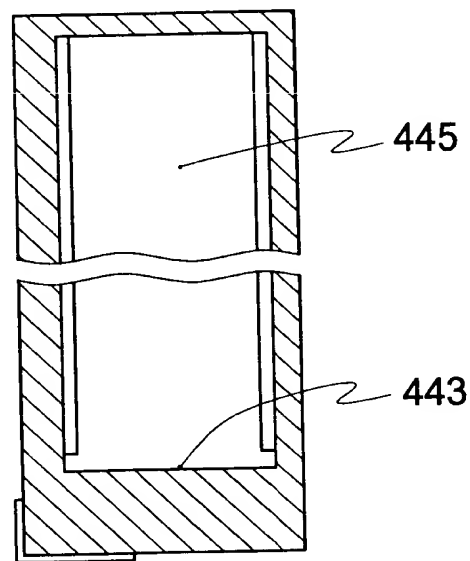


FIG. 47(b)

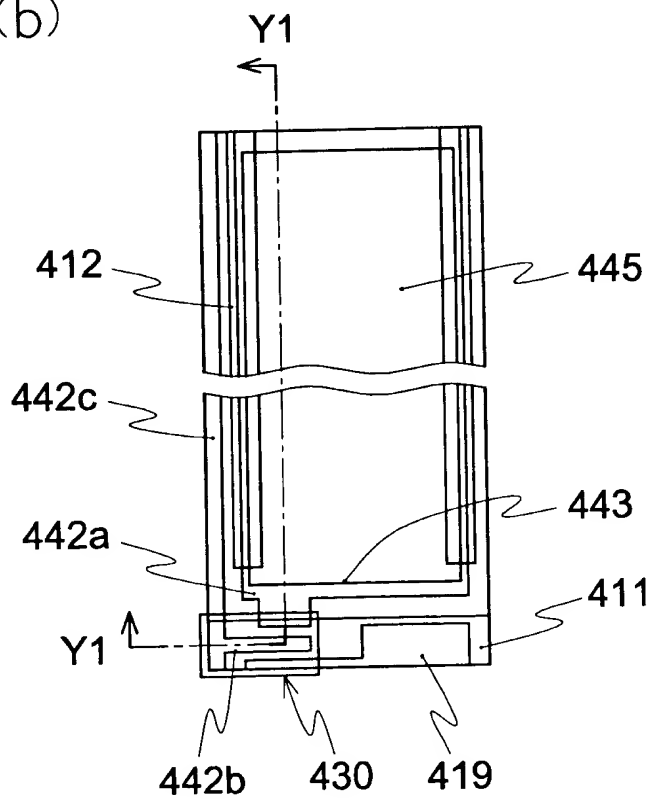


FIG. 48

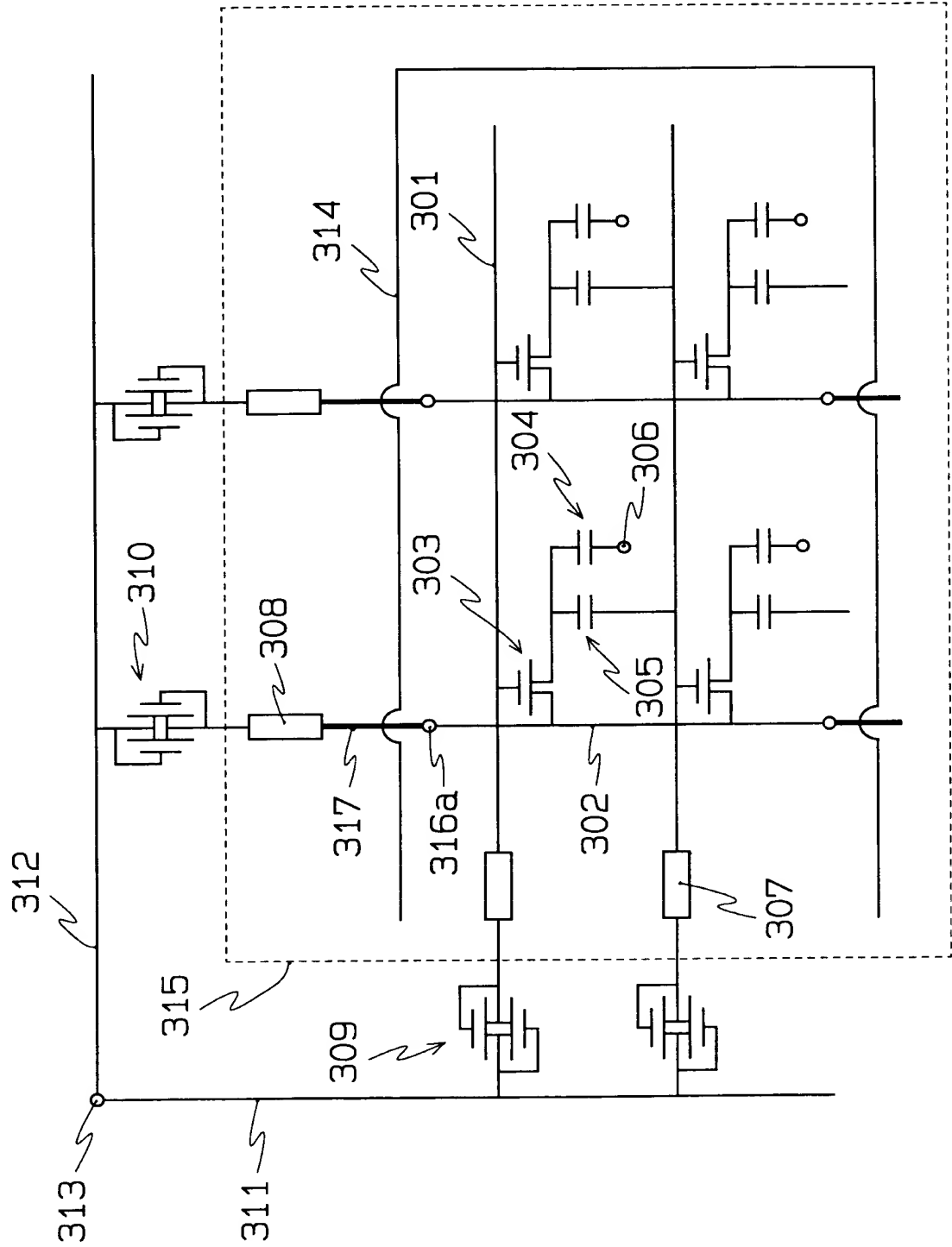


FIG. 49

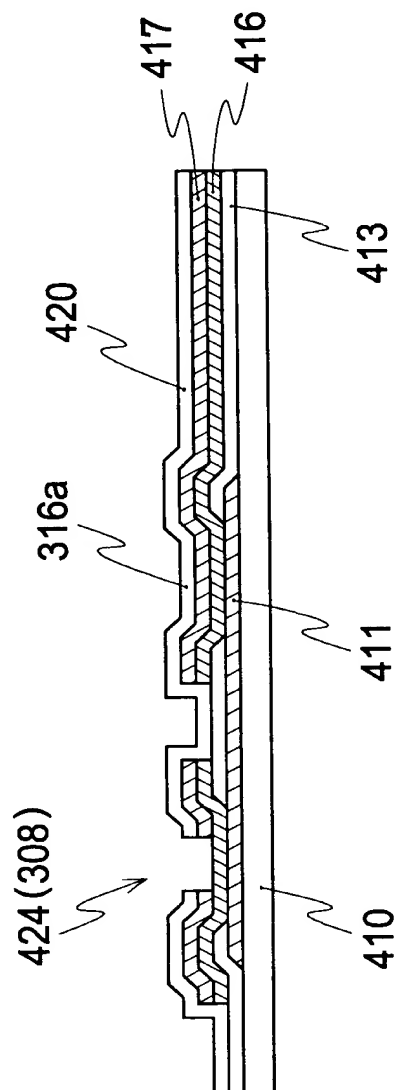


FIG. 50

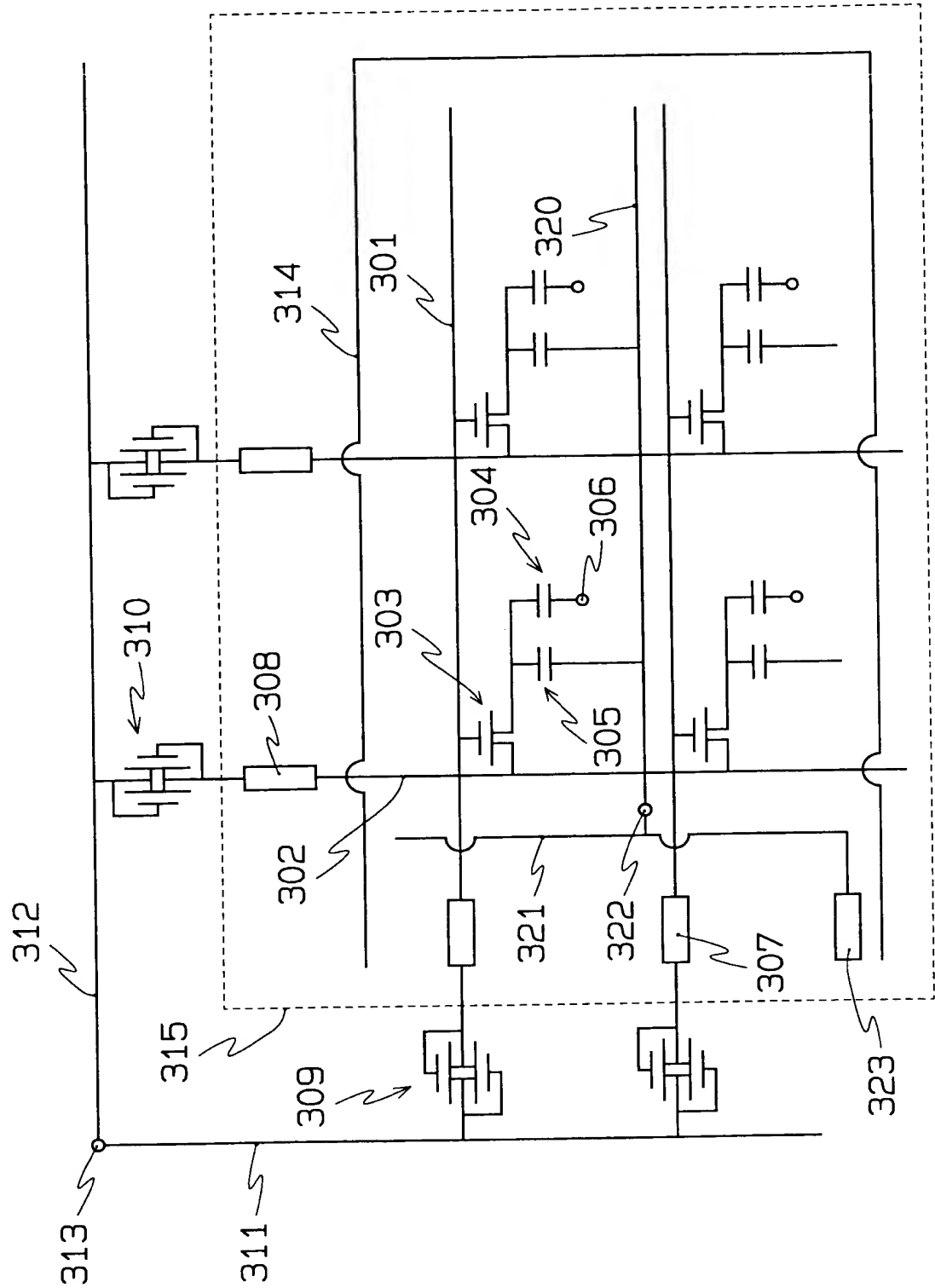


FIG. 51

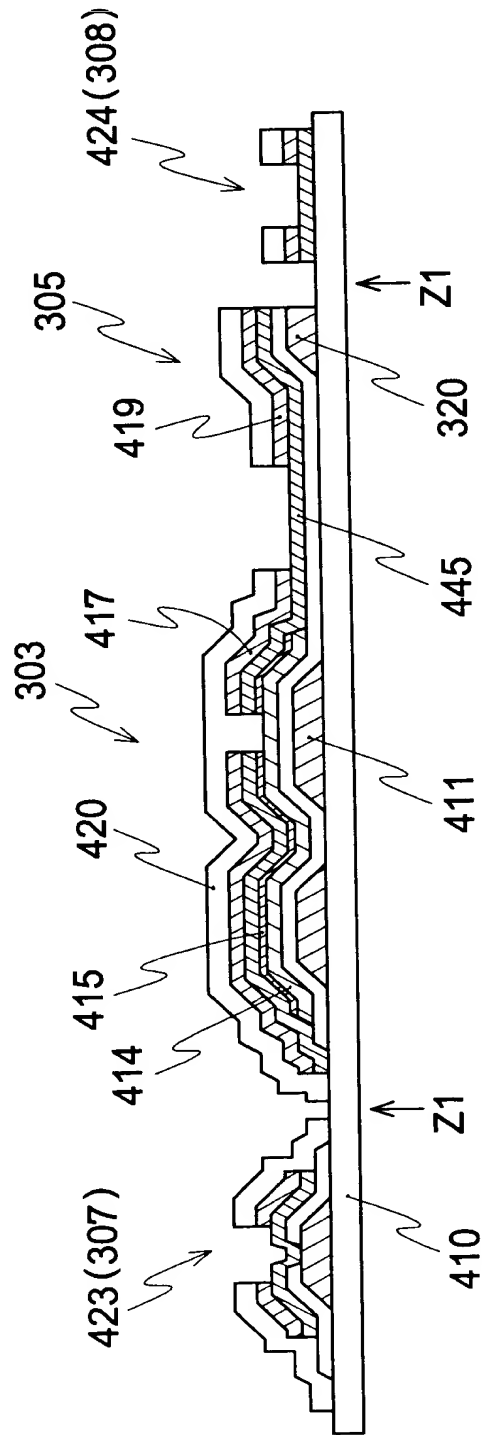


FIG. 52(a)

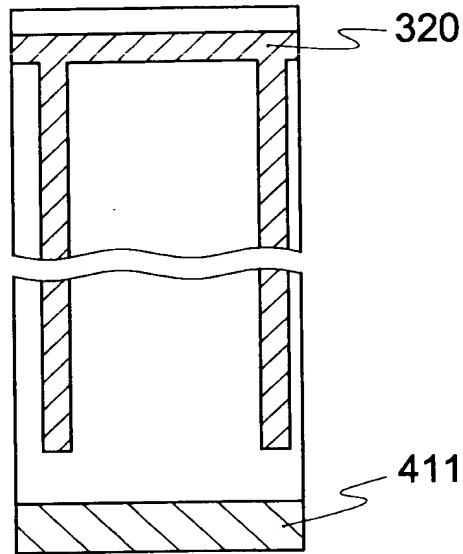


FIG. 52(b)

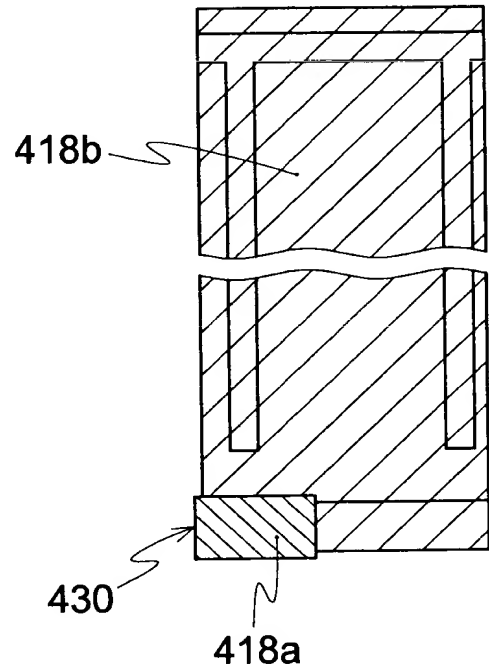


FIG. 52(c)

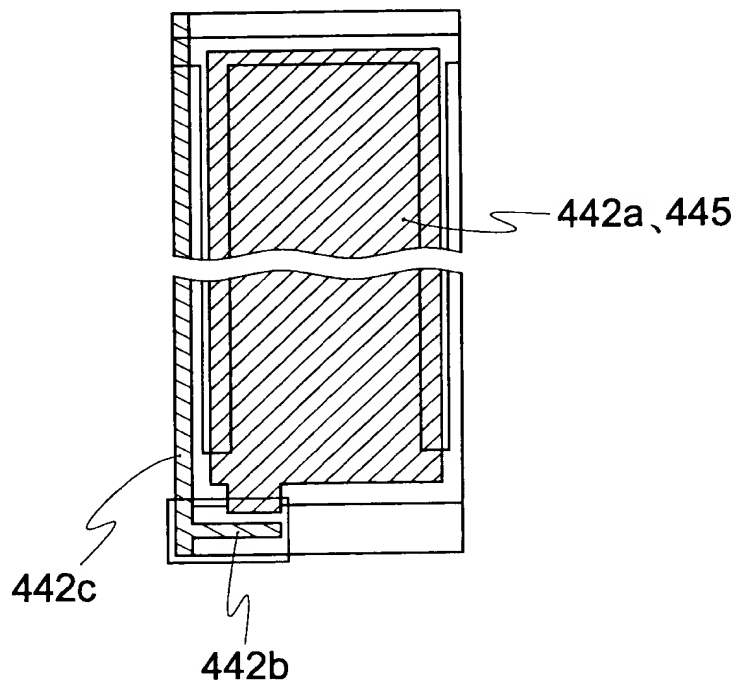


FIG. 53(a)

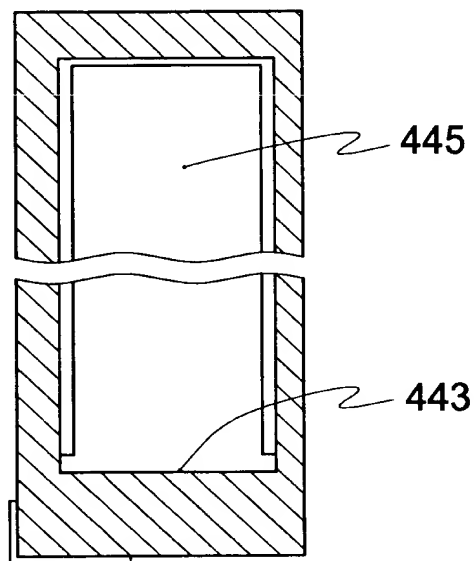


FIG. 53(b)

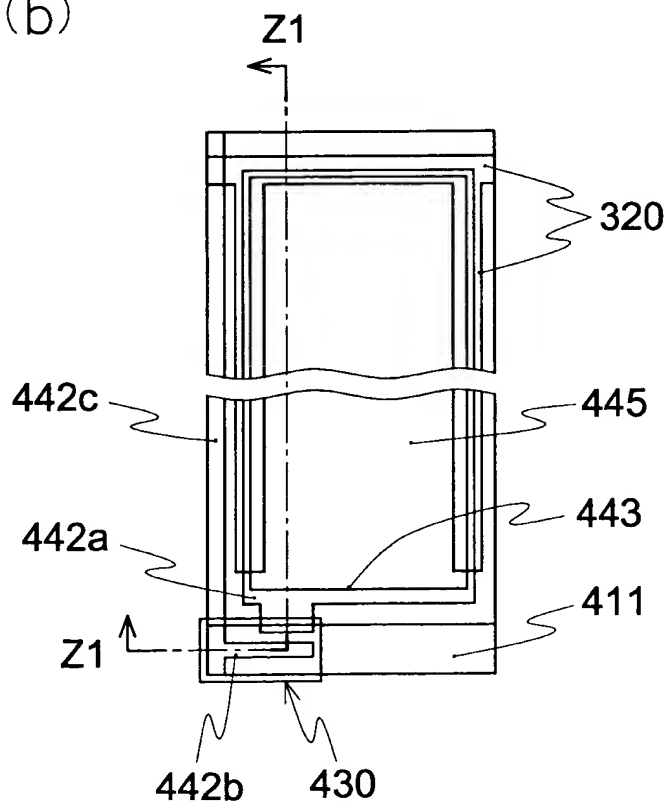




FIG. 54

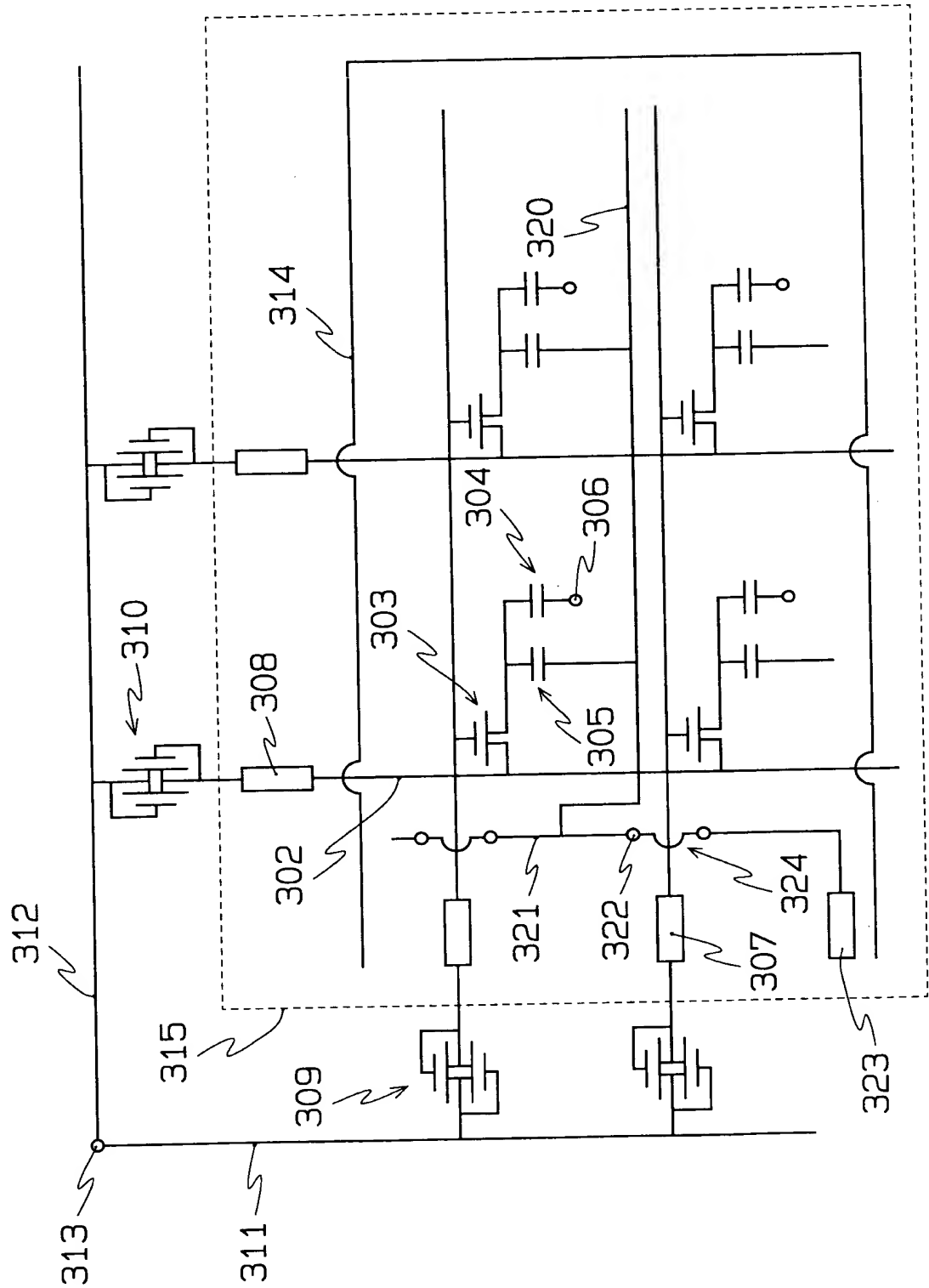


FIG. 55

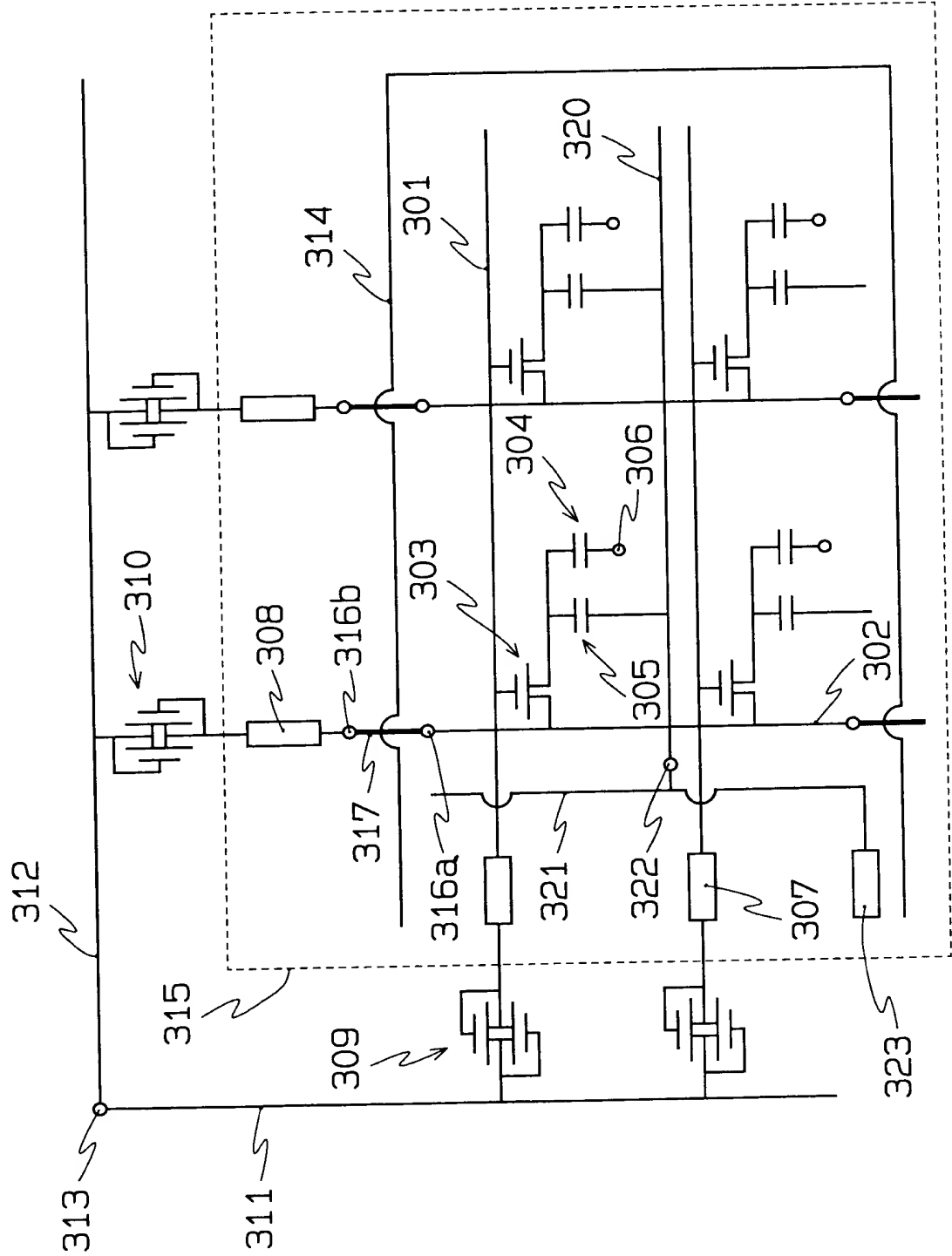




FIG. 57

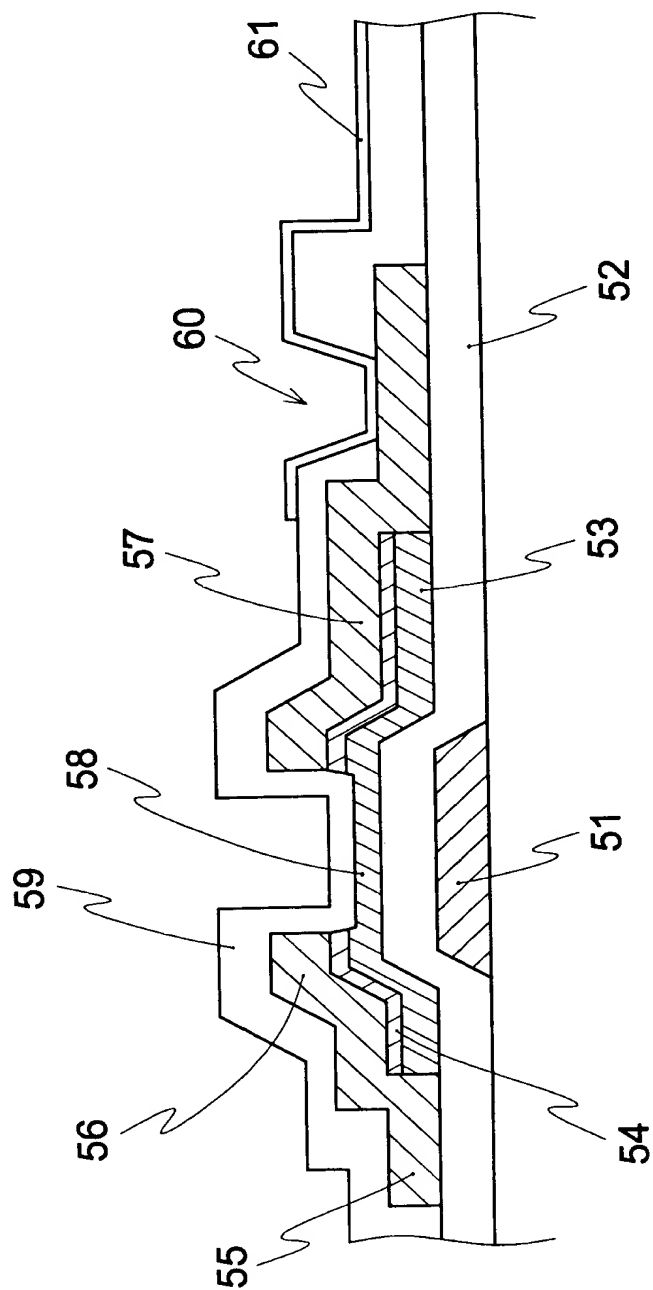


FIG. 58

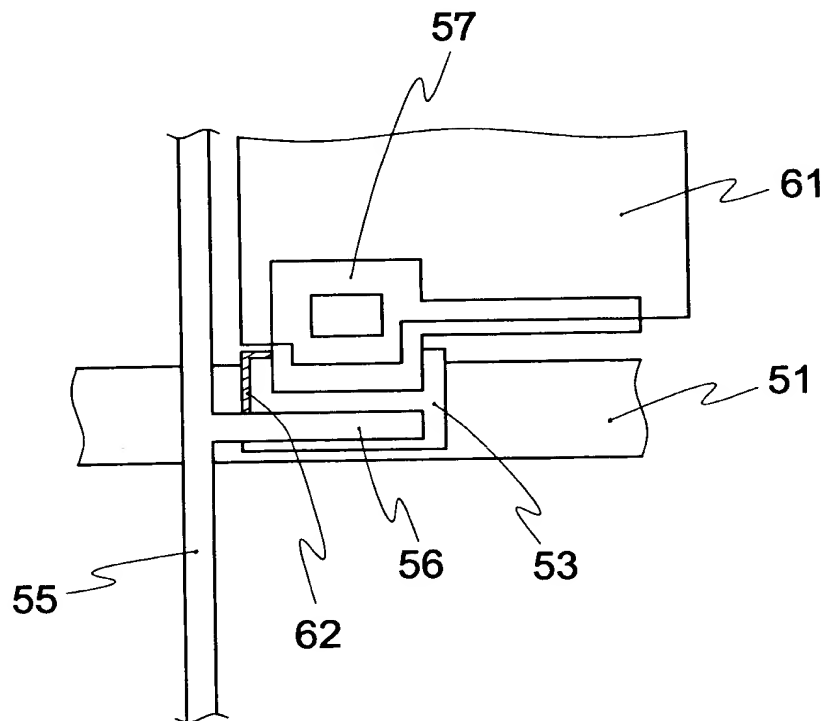


FIG. 59(a)

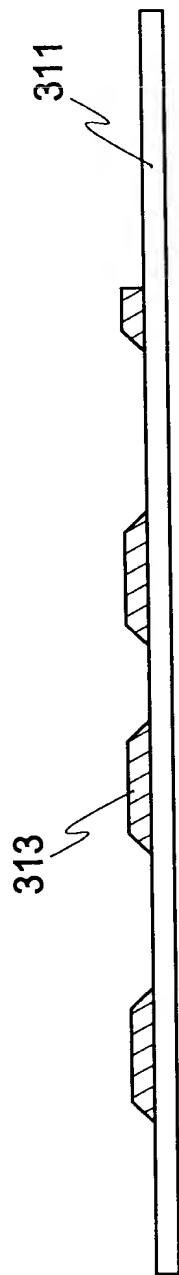


FIG. 59(b)

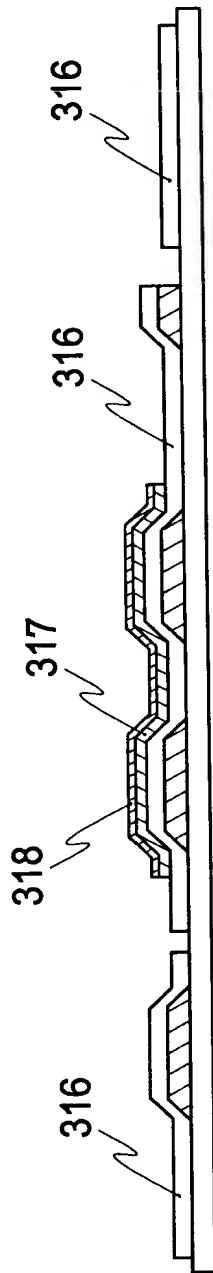


FIG. 59(c)

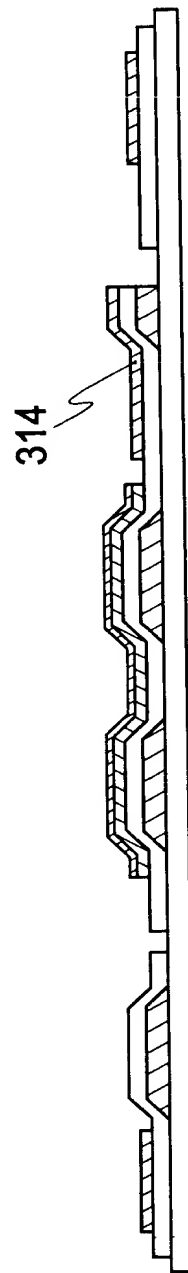


FIG. 60(a)

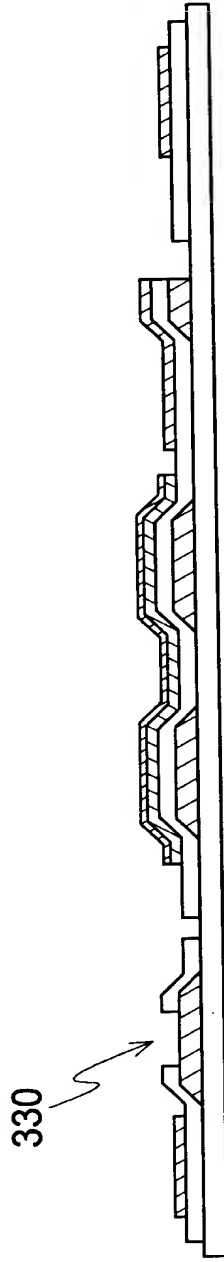


FIG. 60(b)

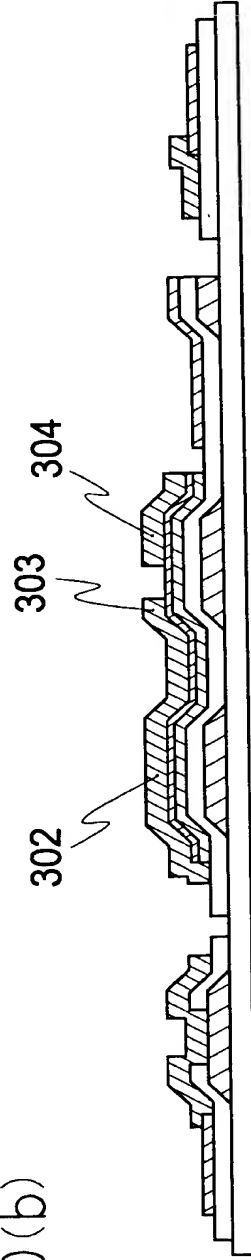


FIG. 60(c)

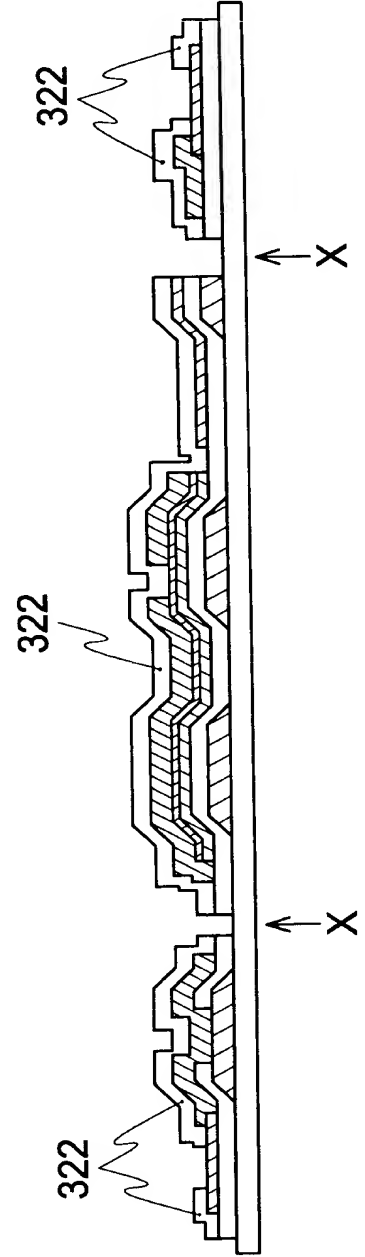


FIG. 61(a)

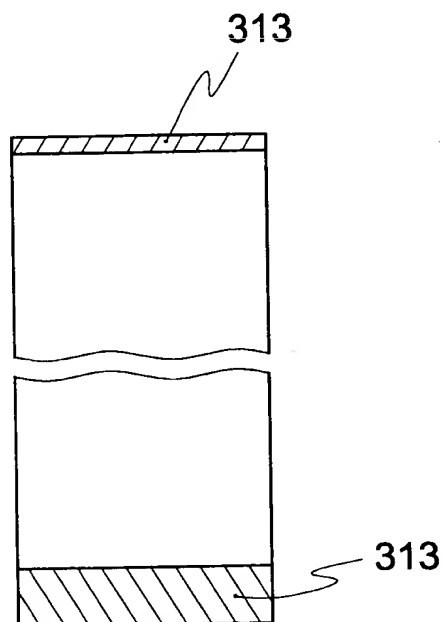


FIG. 61(b)

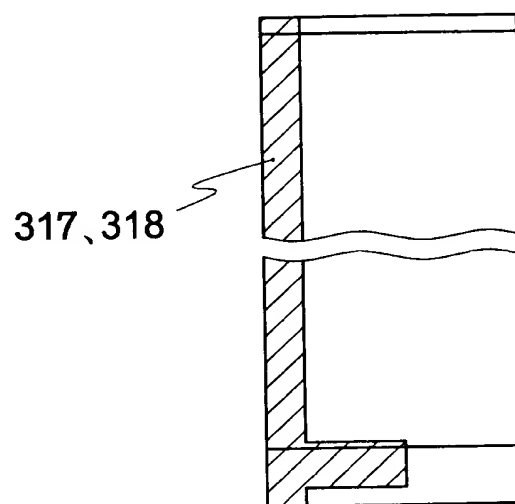


FIG. 61(c)

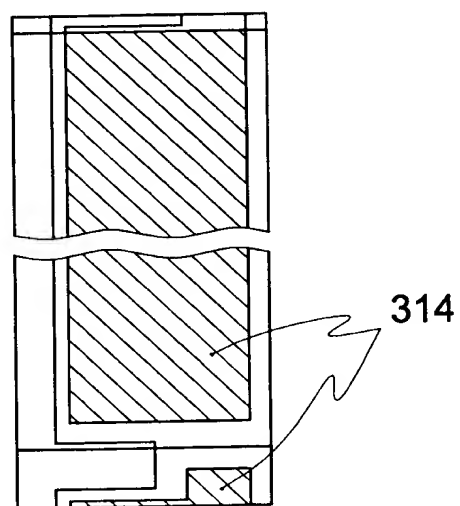


FIG. 61(d)

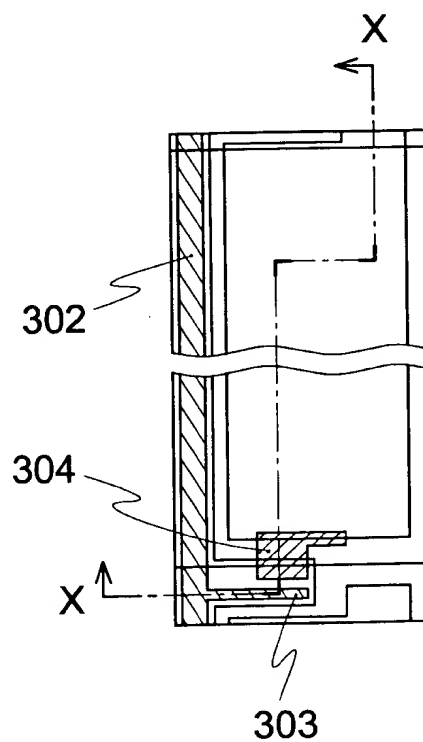




FIG. 62(a)

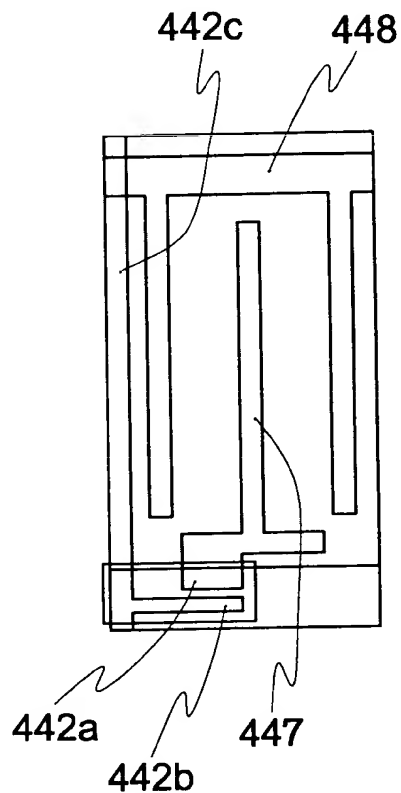


FIG. 62(b)

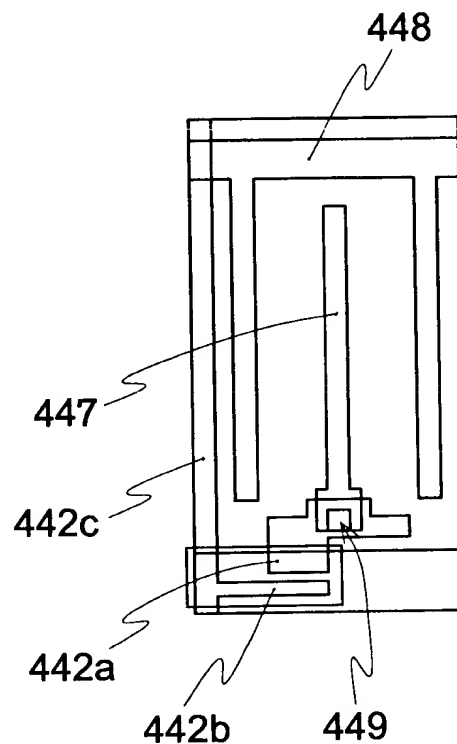


FIG. 62(c)

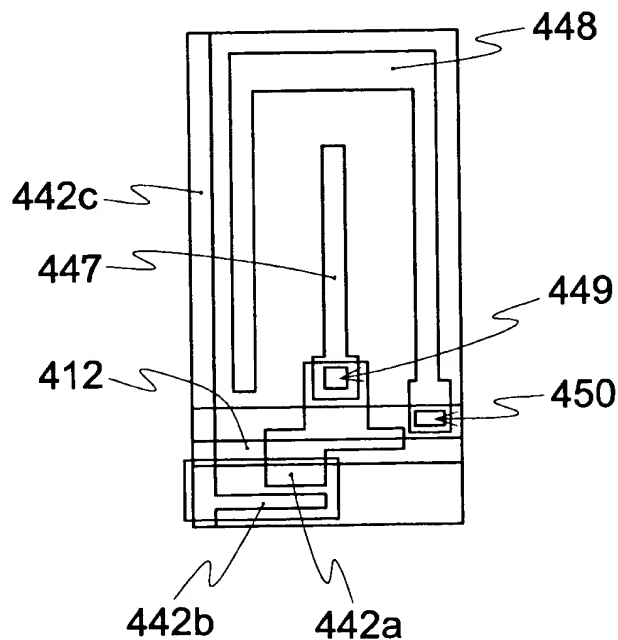


FIG. 63(a)

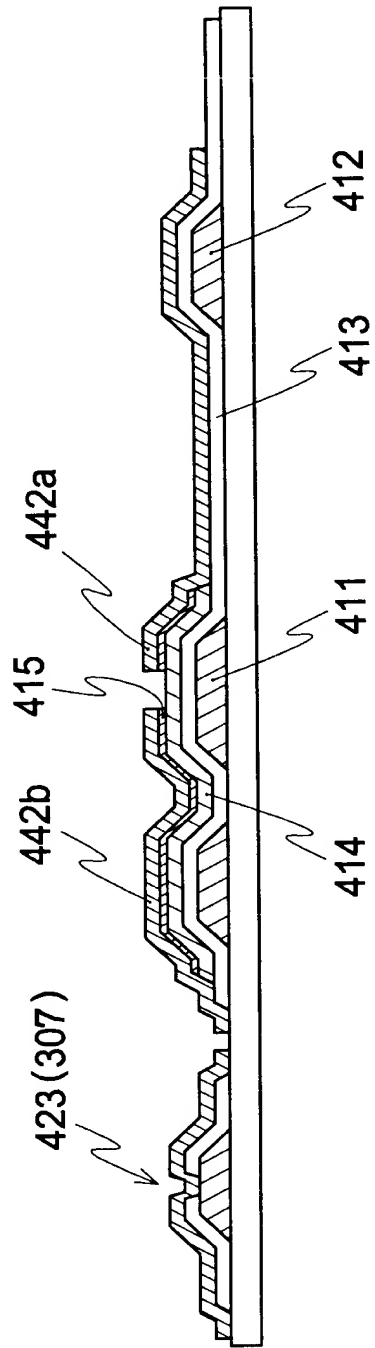


FIG. 63(b)

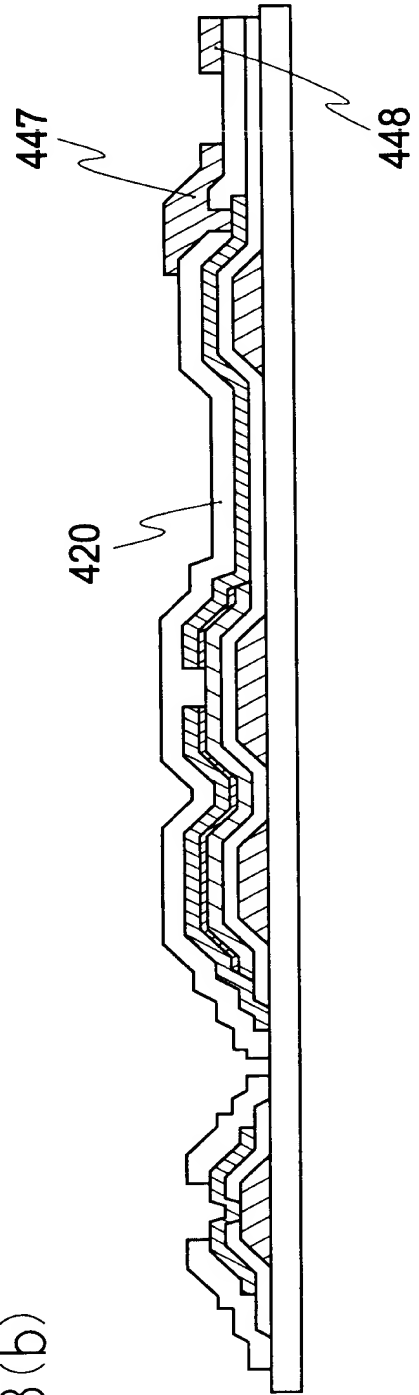


FIG. 64

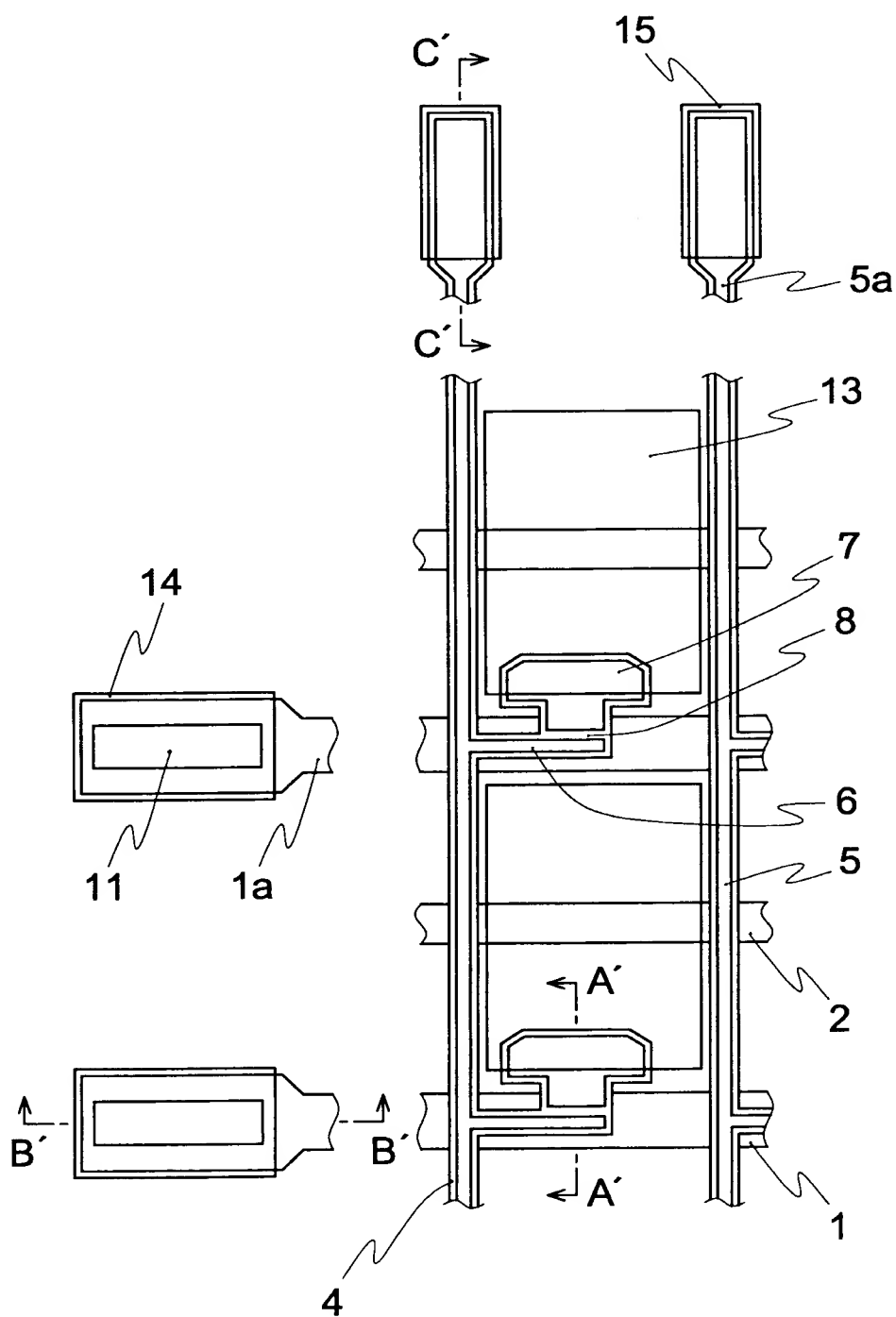


FIG. 65(a)

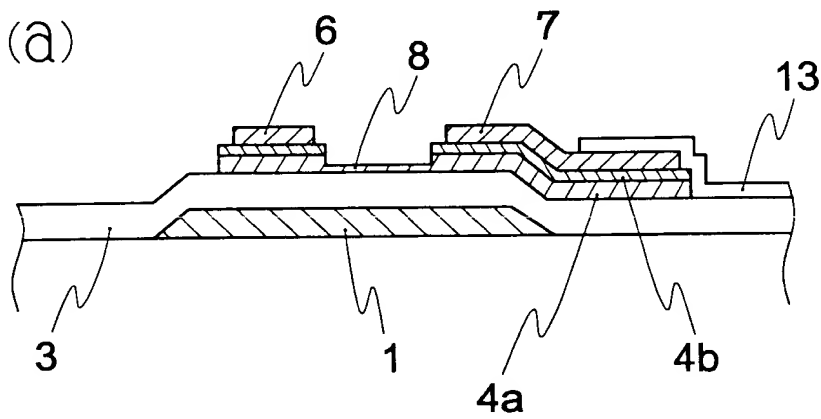


FIG. 65(b)

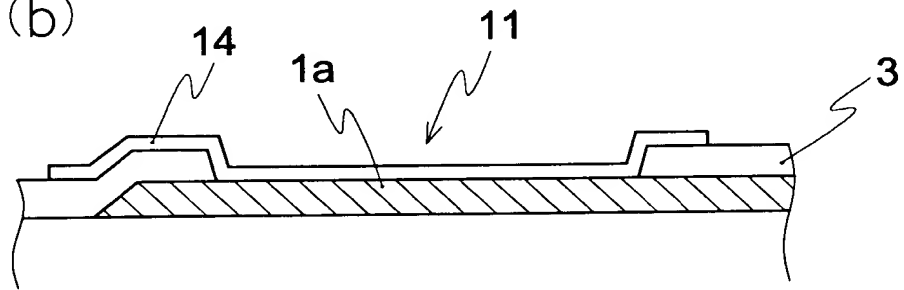


FIG. 65(c)

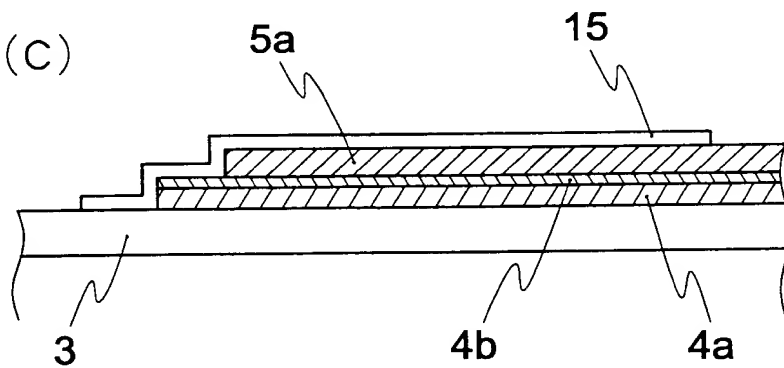


FIG. 65(d)

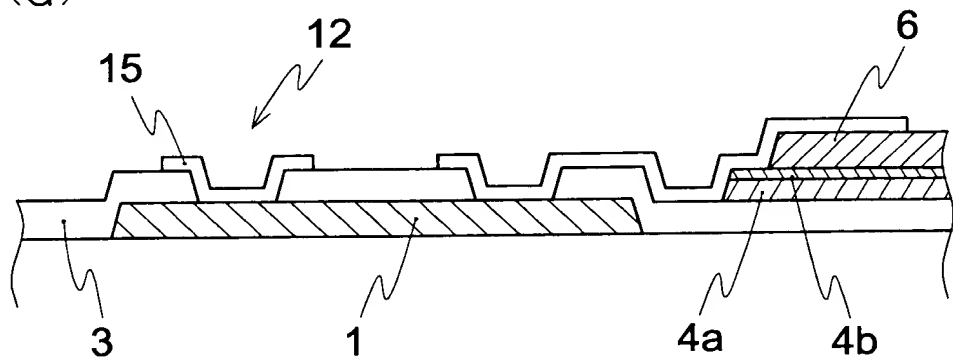


FIG. 66

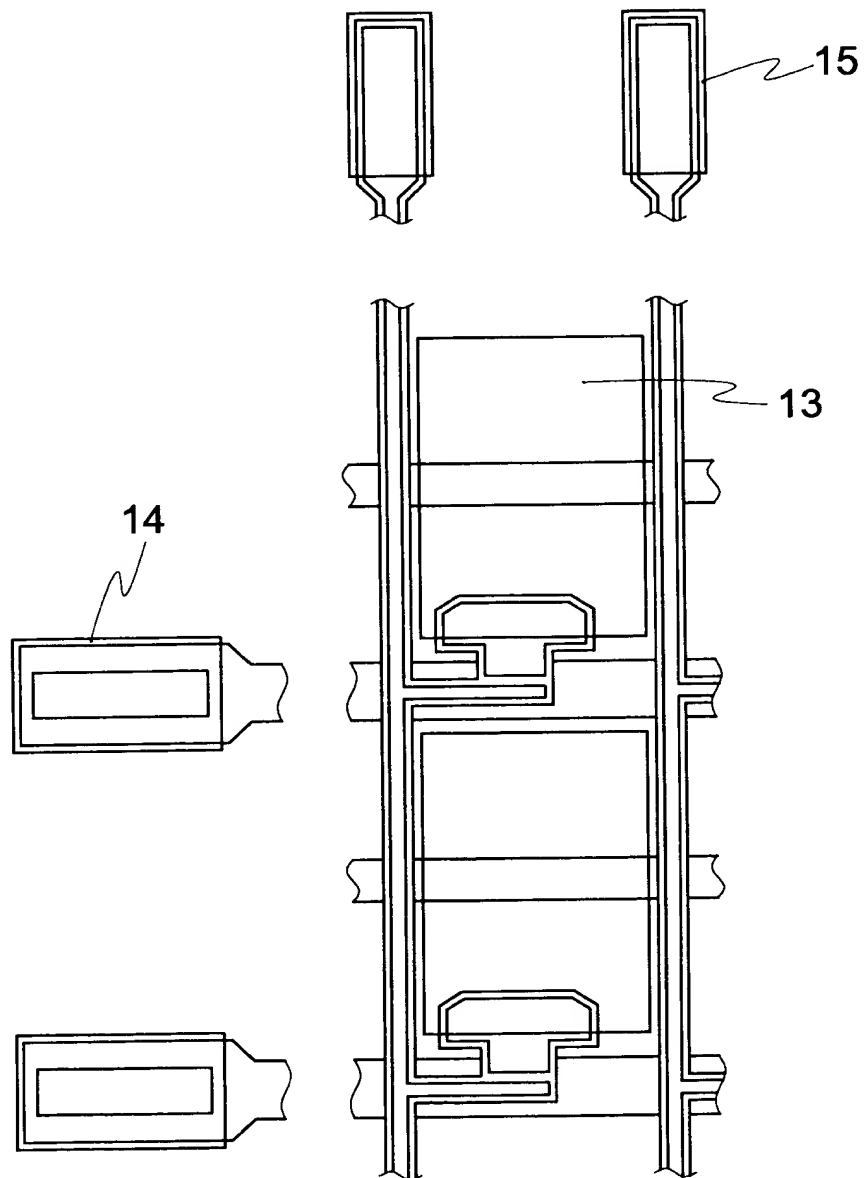


FIG. 67

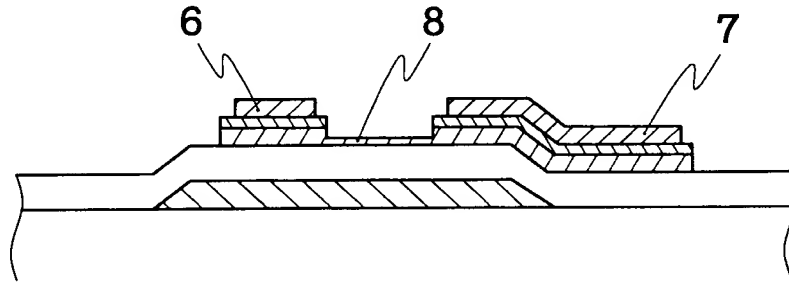


FIG. 68

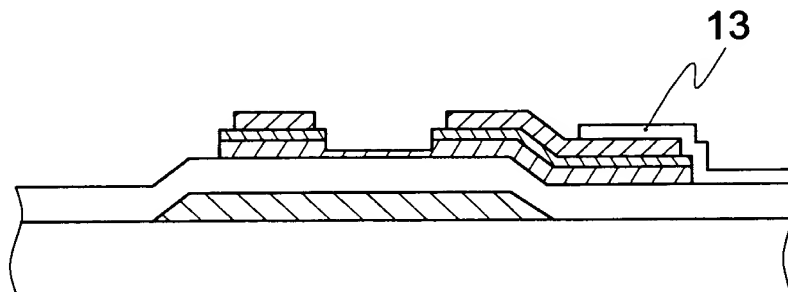


FIG. 69

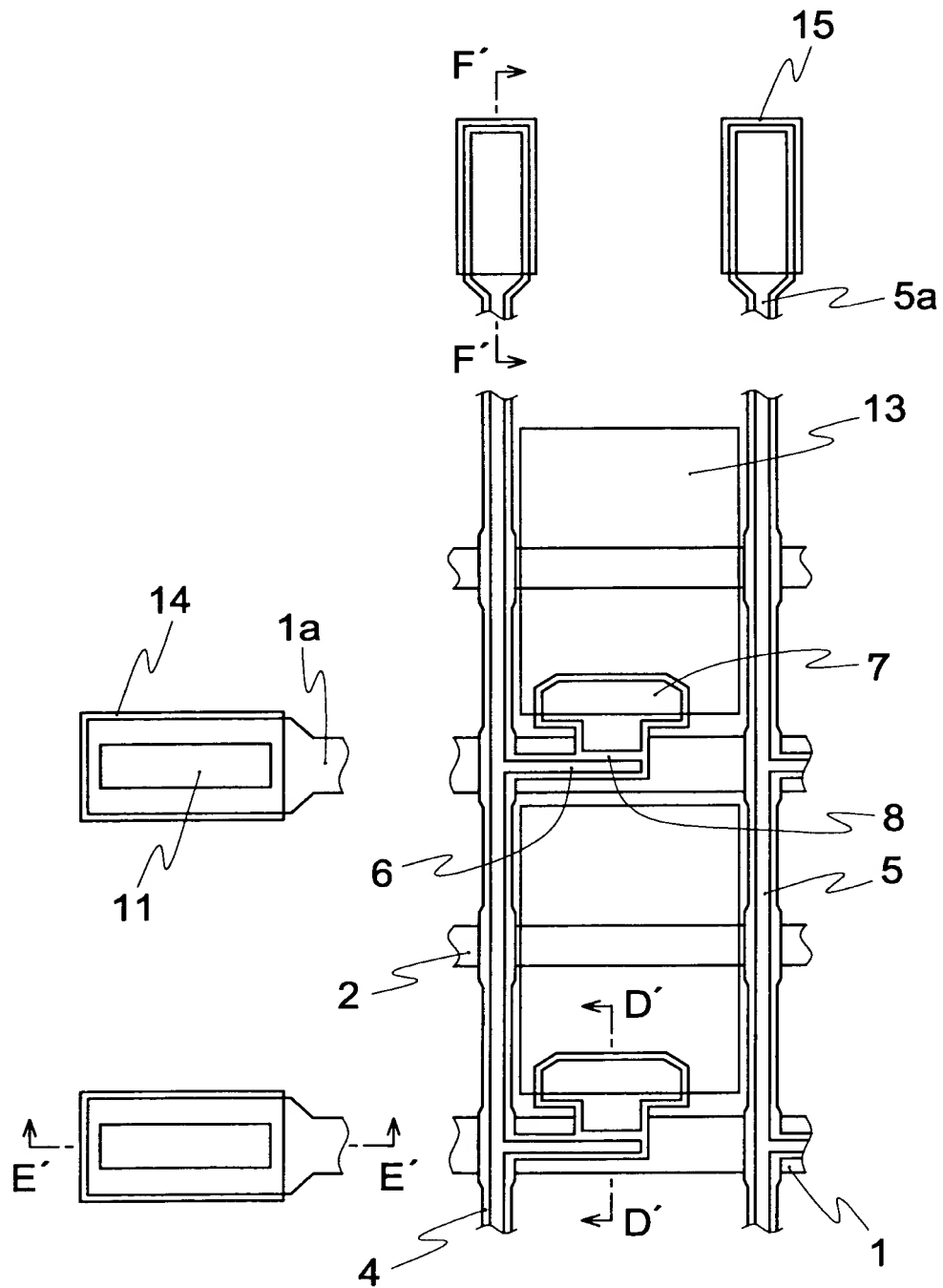
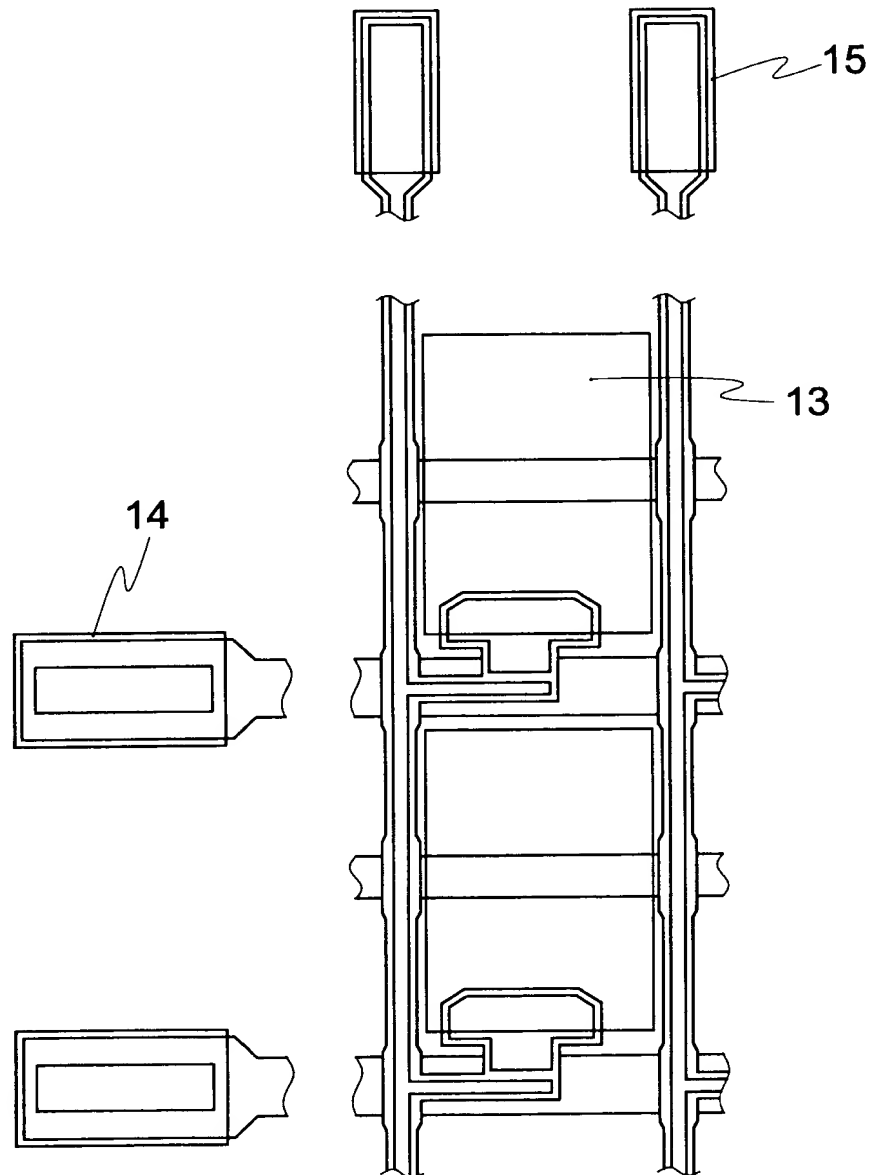


FIG. 70





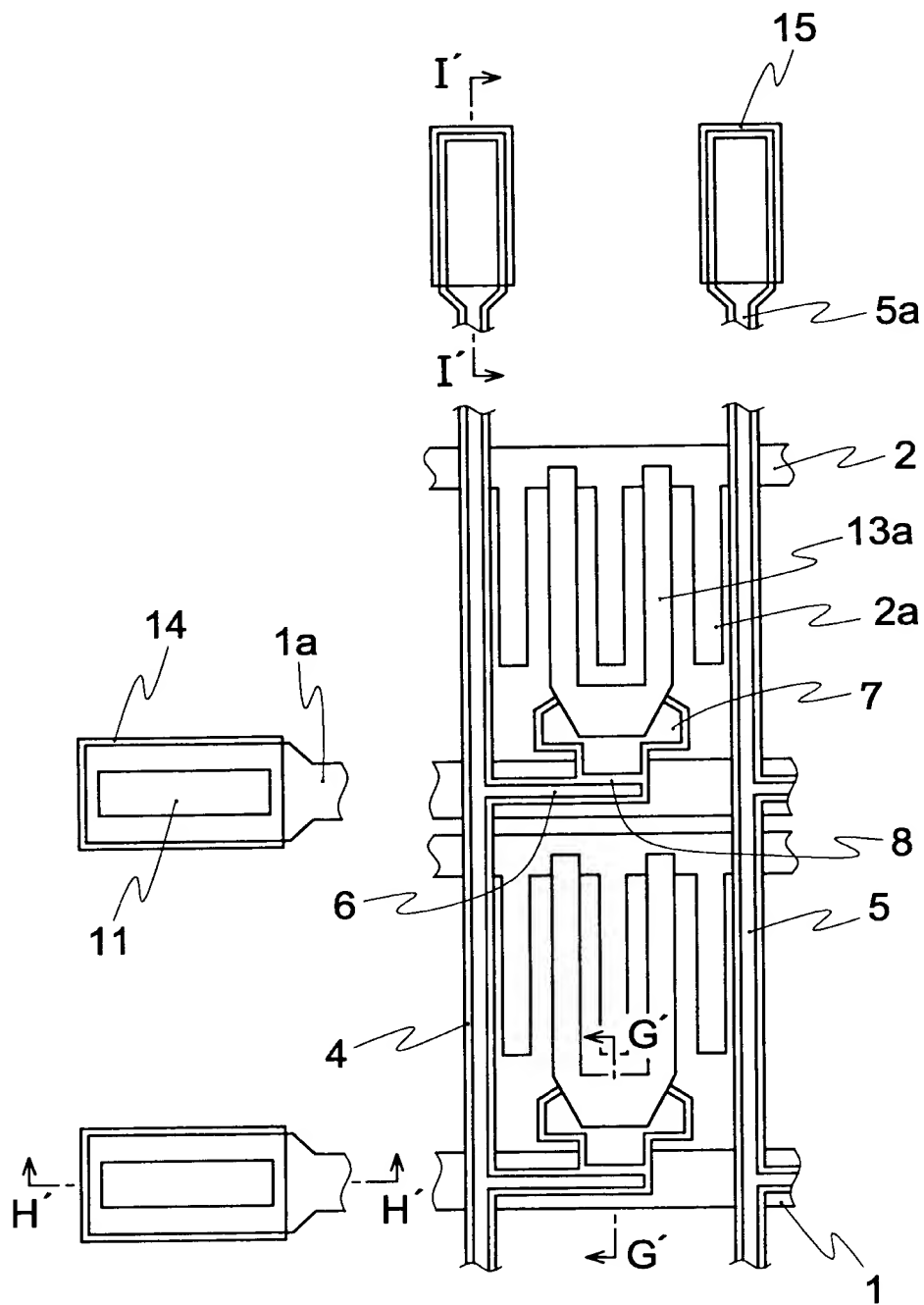


FIG. 72

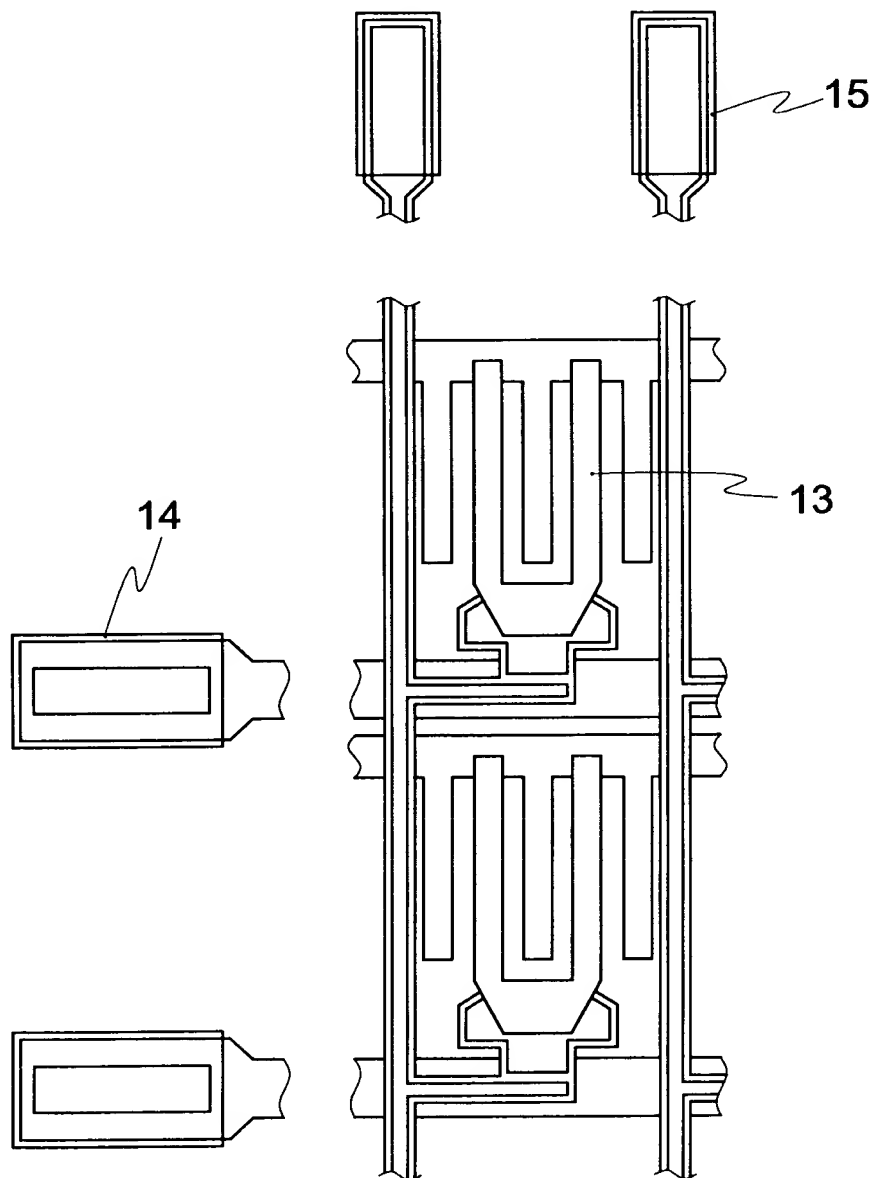


FIG. 73

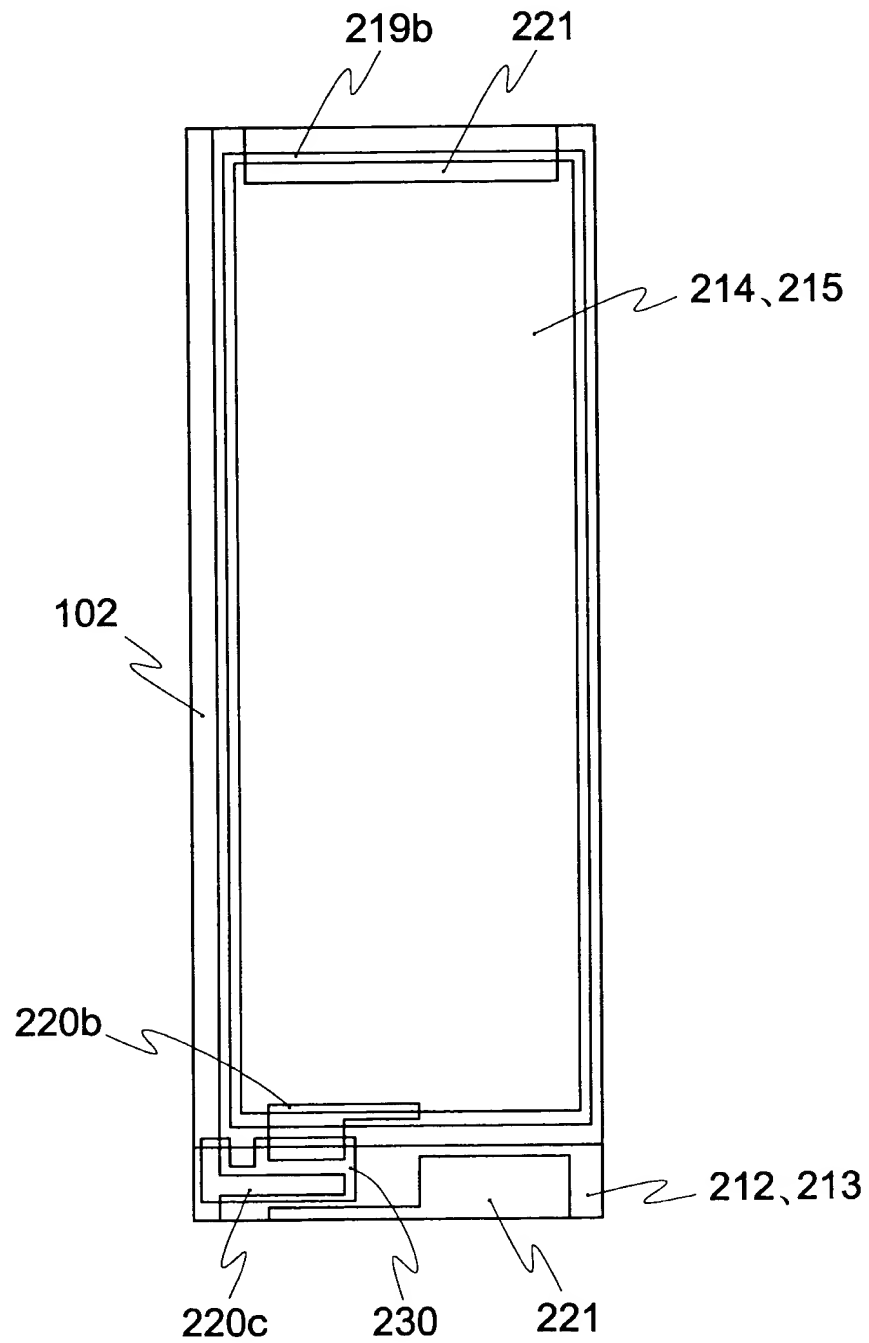


FIG. 74

